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TECHNOPROBE

Italy | Technology | Semicondocturs

CFA Institute Research Challenge 2026

Recommendation: **HOLD**

Date	31/01/2026
Current Price	15.63 €
Target Price	15.66 €

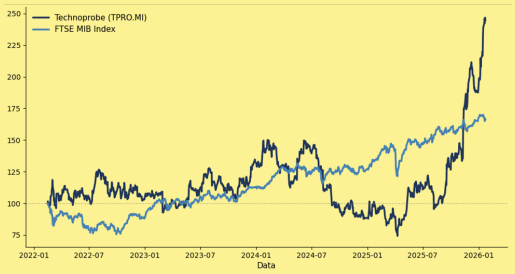
Stock Data

First trading day	15 / 02 / 2022
52-Week High	16,60 €
52-Week Low	4,7 €
Ticker	TPRO
Stock Exchange	Euronext Milan (BIT)

Market Data

Shares Outstading	647M
Market Capitalization	10.21B
EPS	0,11
Free Float	16%

Stock Performance



Shareholder's Structure

	Share
T-PLUS S.p.A.	63,5%
Alba Europe	6,01%
Teradyne	10,0%
Advantest	2,50%
Treasury Shares	2,0%
Free Float	16%

Investment Summary

Technoprobe: The end of the run (for now)

The analysis for Technoprobe S.p.A. (TPRO) starts with a HOLD recommendation and a 1-year target price of 15.53 €, that aligns with the actual traded price range. Technoprobe's market cap stands at 10.4B, with consolidated revenues at 534M as of FY24. We believe the current Technoprobe's valuation to be close to its fundamental value, following a sharp rally in the last two months, in which TPRO has risen from 12.50 € to 15.70 € (+24%), as the company benefited from the actual market momentum tied to the AI sector and the high growth expectations in the future. Crucially, our rating does not reflect any corporate weakness, but is driven exclusively by the current valuation having already discounted the AI euphoria. Consequently, notwithstanding the company's strategic positioning and unique value proposition, the current absence of a significant margin of safety leads us to conclude that the stock is fairly priced, suggesting a holding approach for a more attractive entry point.

Business: Ready for Innovation

Technoprobe stands as the second probe card manufacturer in the world, serving as a vital link in the semiconductor value chain through its comprehensive vertical integration: Technoprobe's unique value proposition is, indeed, anchored in its vertical integration and leadership in Vertical MEMS probe cards, where it commands a 60% market share, a proprietary technology essential for testing advanced sub-3nm chip architectures. Currently, TPRO is executing a structural pivot from cyclical consumer markets toward high-growth AI and data center infrastructure, with the AI segment projected to become its dominant revenue contributor.

Transition toward a "Design-Win" Driven Model

The strategic pivot toward AI and High-Performance Computing (HPC) facilitates Technoprobe's transition from volatile, short-cycle consumer markets to a more predictable and stable order flow throughout the entire lifecycle of chip architectures, supported by multi-year contracts typical of this sector. This increased customer 'stickiness' significantly mitigates the historically 'lumpy' nature of semiconductor revenues, enhancing operational cash flow stability and strengthening the company's financial resilience across economic cycles. Furthermore, the increasing complexity of AI-driven testing requires higher probe needle density, allowing Technoprobe to exert superior pricing power. In our view, this margin-accretive shift toward high-value-added solutions will drive a fundamental re-rating of the company's earnings quality as it aligns with pure-play AI testing peers

Strategic CapEx: Investing Ahead of the Curve

Technoprobe's capital expenditure strategy is a cornerstone of its competitive moat, adopting an "invest-ahead-of-the-curve" philosophy, the company has prioritized expanding its Vertical MEMS capabilities and completing the new Cernusco Lombardone production hub to handle sub-3nm architectures. This intensive investment cycle, including an extraordinary €200-250 million plan for 2026-2027 to capture AI-driven demand, can be entirely self-funded by a robust net cash position of over €600 million.

Valuation

Our fi nal 1-year target price of €15.53 is derived from a weighted valuation approach, assigning 80% to a two-stage DCF model and 20% to a Relative Analysis. We prioritized the DCF as it is inherently more reliable for the semiconductor industry, allowing us to model structural growth drivers and the "complexity premium" associated with Moore's Law—factors that static multiples often fail to capture. This methodology accurately refl ects Technoprobe's heavy Capex investments and its pivotal transition toward the AI segment. The relative component complements this analysis by anchoring the target to peer fundamentals, providing a necessary statistical balance to our long-term projections.

Exhibit 1:
Technoprobe key financials

Exhibit 2:
Technoprobe Global Presence

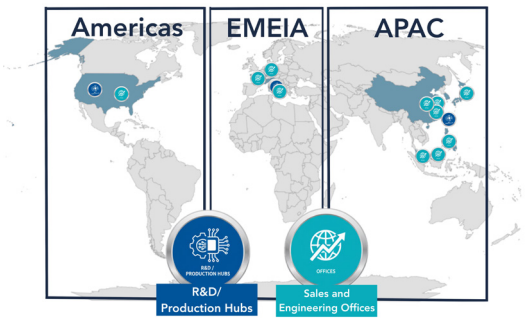


Exhibit 3:
Prociess Flow

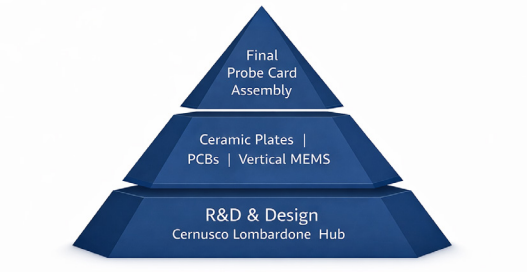


Exhibit 4:
Shareholder's Structure

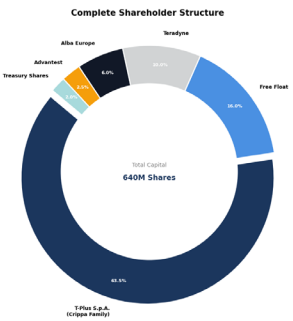


Exhibit 5:
Key Revenue Drivers

The Bridge between wafer fabrication and final device performance

Founded all the way back in 1996 (Appendix 01), Technophobe is an Italian join stock company that design, develop and produce probe cards. The company has global presence with offices and R&D centres around the world - from USA all the way to China - and it's the second largest manufacturer of probe cards in the world. What the company offers is the biggest competitive advantage it has, and that is a final answer for the technological world: ensuring proper functioning of chips. With its proven heritage of innovation, strategic positioning, and well-established history, Technoprobe continues to make a significant contribution to the semiconductor probe card sector.

Business Model

Core operating: The business model is vertically integrated operating in three sectors: Probe Cards, Wafer-level probing solutions and Final Testing (Exhibit 3) - managing the entire process of production, from designing and manufacturing to assembly of probe cards. The smooth running of the process is ensured through the main component of its primary activity: in-hose production of key elements including Contact Probes, Vertical MEMS and Ceramic Plates and PCBs, all developed internally to reduce costs and boost performance. Important adjunct of the model is the high focus put on investments in technologies and R&D activities. Final testing represents the last stage of the semiconductor manufacturing process where packaged chips are electrically tested to ensure they are fully functional before being integrated into electronic devices. It is critical because it identifies defects introduced during assembly, preventing faulty chips from reaching end-users. Technoprobe focuses on high-value-added components for this stage, such as Pogo Pins for test sockets

Value proposition and differentiation: The value of the company is built on delivering high-performance (Appendix 20), tailor-made solutions and centers around its position of being critical, high-technology partner and supplier for semiconductor manufacturers. As a leading innovator primarily focusing on Vertical MEMS, Technoprobe allow itself to be differentiated from the competence in the industry, maintaining its stable financial position and constant innovation. (Appendix 11)

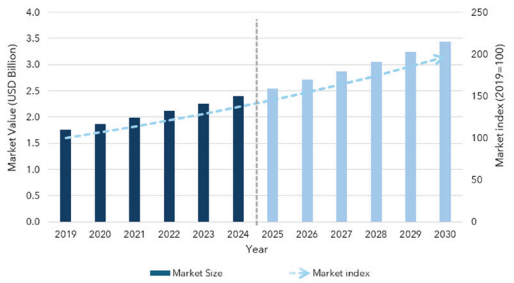
Target Market Achieved through Strategic partnerships: World's leading microelectronics, IT and digital companies within the semiconductor probe cards market, producing variety of electronic devices are who Technoprobe produces for. Technoprobe's global presence (Exhibit 02) is one of the main competitive advantages it has in serving the market. The company has established long-standing relationship through several M&A projects in the recent years with purpose to expand the expertise and ensure high-quality and timely delivery of end products.

Mergers and Acquisitions: Technoprobe M&A (Appendix 12) approach is based on building an "open ecosystem" driven by the desire to maintain their competitive advantage through acquisition of capabilities, skills, data and knowledge and therefore better meet new opportunities and uncertainties. Starting by firstly acquiring Microfabrica Inc. in 2019 to establishing better control in their activities over the Atlantic, later followed by two important acquisitions of Harbor Electronics and MW Plasma in 2023. In 2024 Technoprobe acquired the DIS business department of Teradyne and additionally Teradyne acquiring 10% stake in Technoprobe. With purpose to form a commercial and strategic partnership Technoprobe has signed multiple agreements with Advantest Europe GmbH, at the beginning of 2025 for expending their competences. The completion of M&A projects during the same year did not stop there, since Technoprobe has acquired 9.37% of Innostar Service Inc based in Taiwan, allowing Technoprobe to trade it's share on TPEx, and

Technology-driven, customer-centric Revenue Model

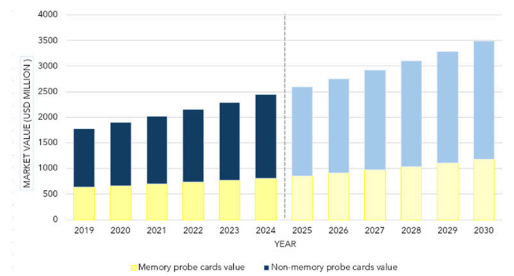
The company's revenue base is primarily driven by semiconductor production volumes, increasing device complexity and long-standing customer relationship (Exhibit 3). Over the past cycle it reflects strong expansion supported by strong demand for advanced semiconductor testing solutions, and at pre-cycle levels, revenues have more than tripled despite a temporary slowdown linked to a broader semiconductor market normalization. This confirms company's ability to capture structural growth drivers while remaining exposed to industry cyclicality. Looking forward, projections imply renewed growth phase and as the growth normalizes, the revenue base is set to evolve toward greater scale and stability, enhancing cash-flow visibility while maintaining sensitivity to semiconductor investment cycles.

Exhibit 6:
Semiconductor Probe Card Market size (2019-2030)



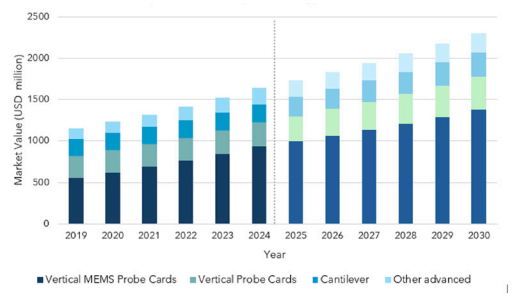
Source: Company Data, Team Estimates

Exhibit 7:
Probe Card by Market Type (2019-2030)



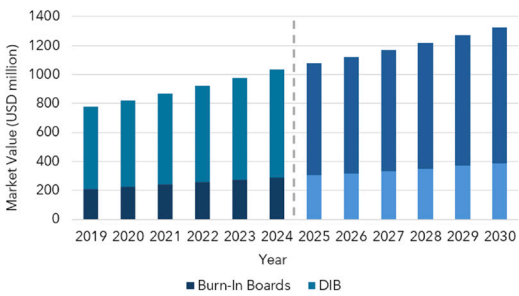
Source: Company Data, Team Estimates

Exhibit 8:
Logic Probe Card by technology (2019-2030)



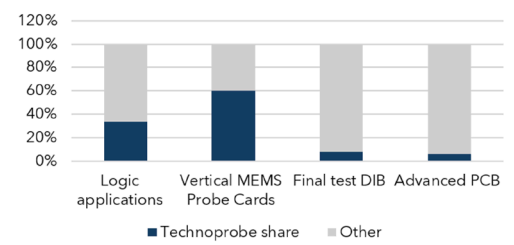
Source: Company Data, Team Estimates

Exhibit 9:
Final testing Market By Technology (2019-2030)



Source: Company Data, Team Estimates

Exhibit 10:
Technoprobe Market Share



Source: Company Data, Team Estimates

Probe Cards as Structurally Critical Node in Semiconductor Testing

Operating in the probe card section of the semiconductor test equipment industry, Technoprobe serves as a vital link between wafer manufacture and device-level validation for both memory and non-memory applications. As of 2024, North America represents the largest end market for probe cards, while Asia Pacific the fastest-growing region. As demonstrated by consistent increase in both the logic and memory probe card sectors, market expansion reflects rising testing complexity and intensity across sophisticated semiconductor devices. High barriers to entry, such as strict quality and reliability standards, long client qualification cycles, high capital intensity, and substantial customization costs, structurally limit the market and create a consolidated competitive landscape. Demand growth is supported by widespread adoption of 5G, AI and IoT, shift toward toward autonomous driving, expanding data-center investments, advanced packaging, rising OAST activity, growing adoption of MEMS probe cards, and sustained demand for HBM and DRAM. In order to expand its presence along the semiconductor testing value chain while staying rooted in the market's highest value-added segment, the company's portfolio is mainly concentrated on logic probe cards, with a strong emphasis on advanced MEMS-based solutions, particularly Vertical MEMS, while maintaining selective exposure to final testing through Burn-In Boards and Device Interface Boards.

Market Dynamics: Steady Expansion with Visible Growth Normalization

The semiconductor probe card market demonstrates sustained expansion over the 2019-2030 period (Exhibit 6), growing from approximately USD 1.7 billion in 2019 to around USD 2.4 billion by 2024, reflecting a 6.5% CAGR. Rather than a decline in absolute demand, the growth moderation between the two periods indicates a clear normalization after a time of more robust historical expansion. Final testing shows a similar trend (Exhibit 9), with market size increasing at a 5.9% CAGR from over USD 780 million in 2019 to just over USD 1.0 billion in 2024 before slowing to a 3.9% CAGR through 2030. The steady slowdown in both probe cards and final tests suggests that earlier growth benefited from quicker increases in equipment value and testing intensity, whereas the later period shows a shift toward more gradual, steady market expansion as testing infrastructure grows with a larger installed base.

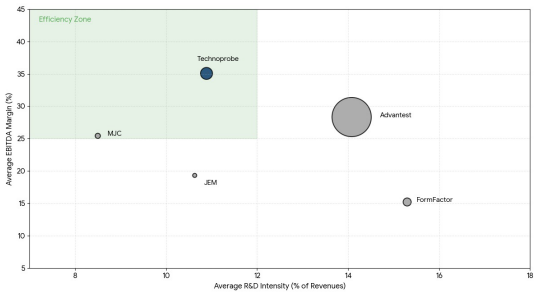
Segment and Technology Mix: Logic-Led Probe Card Growth and Vertical MEMS Outperformance

Within probe cards, logic applications drive faster market expansion during the 2019–2024 period, growing at a 7.3% CAGR compared with 4.3% for memory, indicating higher incremental value contribution from logic-oriented testing. This gap closes between 2025 and 2030 as logic slows to 5.9% and memory growth picks up speed to 6.6%, indicating a balance of segment contribution rather than a reversal in relative importance. With a 10.9% CAGR through 2024, Vertical MEMS probe cards clearly beat traditional vertical, cantilever, and other advanced probe technologies, which increase at low single-digit rates. Vertical MEMS maintains the largest absolute market value increase, highlighting its role as the primary technology absorbing incremental logic probe card demand throughout the entire period. However, the subsequent compression in growth rates across all logic probe technologies through 2030 points to broader adoption and maturation effects.

Technology-driven, customer-centric Revenue Model

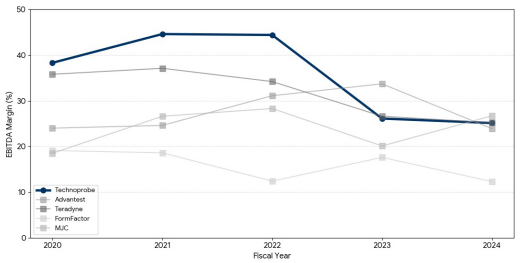
Technoprobe's market share profile (Exhibit 10) indicates a concentrated positioning in segments that exhibit both higher historical growth and sustained absolute expansion. Strong alignment with the fastest-growing probe card technology throughout the 2019–2024 period is demonstrated by the company's roughly 60% share in Vertical MEMS probe cards, which considerably exceeds its roughly one-third share in overall logic applications. As seen by final test CAGRs falling to the high-single-digit to mid-single-digit range in the later period, Technoprobe's single-digit exposure to final testing segments like DIB and advanced PCB, corresponds with those markets slower growth rates and more noticeable deceleration. This distribution suggests that the company's revenue mix is structurally weighted toward probe card technologies, where market growth has been fuelled

Exhibit 11:
Structural Efficiency: 4- year average analysis (2021-2024)



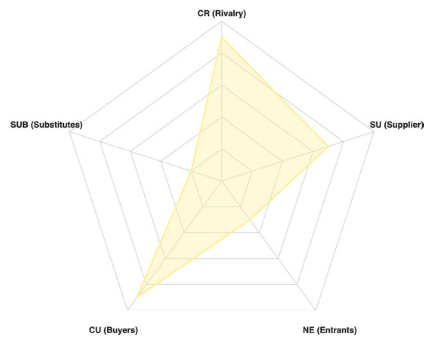
Source: Company Data, Team Estimates

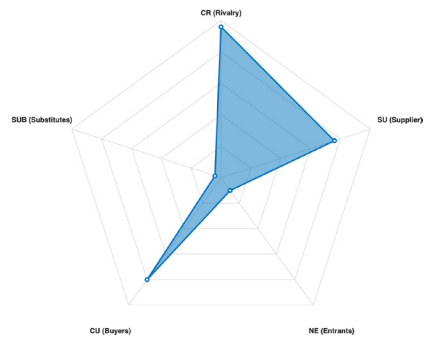
Exhibit 12:
EBITDA margin evolution



Source: Company Data, Team Estimates

Exhibit 13:
Porter Five Forces Analysis





Source: Company Data, Team Estimates

Structural efficiency and superior value capture

Our multi-year structural analysis (2021-2024) confirms Technoprobe as a unique industry outlier, positioned firmly within the "Efficiency Zone" by converting technological innovation into operational profit more effectively than its primary peers. While competitors like FormFactor face significant margin compression despite a higher average R&D intensity of 15.3%, Technoprobe maintains an elite 35.1% average EBITDA margin with a leaner 10.9% R&D commitment. This structural efficiency validates the thesis that TPRO's vertical integration serves as a superior value-capture engine rather than just a supply chain safeguard. By shielding proprietary know-how and retaining manufacturing margins in-house, Technoprobe has established a best-in-class efficiency frontier; this ensures that as capacity utilization normalizes with AI-driven demand, the company is poised for disproportionate earnings growth compared to "asset-light" models.

Unmatched R&D prowess and global hubs

Technoprobe operates as a global technological hub, maintaining a sustained investment cycle even during market volatility. In 2024, Technoprobe allocated €63.4 million to R&D (11.7% of revenues), reflecting an 11.6% year-on-year increase. This strategy ensures constant innovation across its four specialized centers, with the headquarters in Cernusco Lombardone acting as the engine for core development.

Strategic Barriers

Unlike its "asset-light" competitors, Technoprobe's model is defined by deep vertical integration. By internally producing key components, such as contact probes, MEMS structures, and ceramic plates, the company protects proprietary manufacturing secrets and ensures supply chain resilience, reducing external dependence on specialized suppliers. This integration allows for a superior Return on Invested Capital (ROIC) and creates a market barrier for new entrants, as it combines high capital intensity with niche technological expertise and know how.

Porter Analysis

Technoprobe's baseline position is defined by a defensive high-barrier duopoly, where intense technical rivalry with FormFactor and high buyer concentration (TSMC, Samsung) are counterbalanced by formidable patent moats that effectively block new entrants (Exhibt C). However, the strategic pivot toward AI-driven revenue fundamentally rewires these competitive forces, transitioning the industry physics from "volume-based" to "value-based" competition. In this AI-centric paradigm, buyer power paradoxically declines: hyperscalers dependent on "first-pass yield" for expensive AI modules become price-insensitive, prioritizing technical perfection over cost. Simultaneously, rivalry intensifies into a binary "winner-takes-all" innovation race, while the extreme complexity of testing 3nm chiplets raises entry earriers from "high" to "insurmountable." The result is a structural fortress (Exhibit D): this shift insulates Technoprobe's expanding 44,5% EBITDA margins and cements its status not merely as a vendor, but as an irreplaceable critical partner in the global AI infrastructure.

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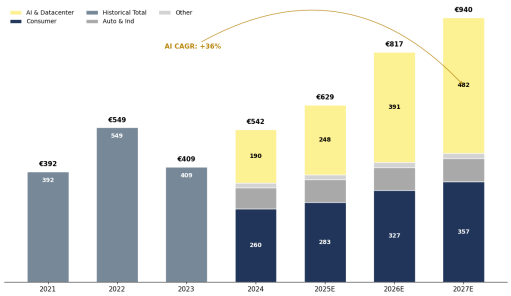
Furthermore, this operational leverage creates a compounding advantage as the semiconductor cycle pivots toward high-complexity AI architectures earnings growth compared to "asset-light" models. Unlike peers reliant on fragmented supply chains, Technoprobe's unified production model drastically reduces iteration cycles for next-generation probe cards, a critical differentiator for hyperscale customers demanding rapid time-to-yield. Consequently, incremental revenue generated during the impending upcycle will accrue to the bottom line with greater velocity, solidifying a "profit sanctuary" that insulates the company against pricing pressures while maximizing free cash flow conversion.

Exhibit 14:
Multi-year Revenue Analysis: Transition toward AI



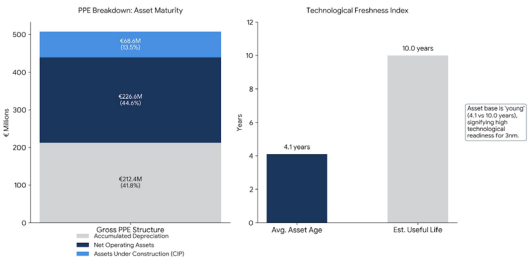
Source: Company Data, Team Estimates

Exhibit 15:
Investment profile

Company	Capex/ Sales (FY23)	Capex/ Sales (FY24)	Investment Profile
Technoprobe (TPRO)	**15.6%**	**14.7%**	**High Intensity**: Focus on Vertical Integration d the expansion of proprietary production hubs (e.g., Cernusco Lombardone)
Micronics Japan (MJC)	~9.5%	~13.5%	**Accelerating**: Significant investment push to scale capacity for HBM and advanced DRAM memory testing.
FormFactor (FORM)	~8.0%	~4.5%	**Asset-Light**: Employs a more flexible manufacturing model with lower reliance on massive physical infrastructure.

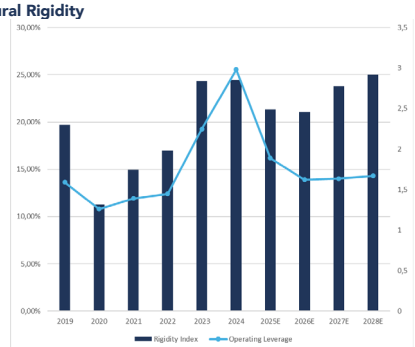
Source: Company Data, Team Estimates, Bloomberg

Exhibit 16:
PPE Structure and Technological Freshness Assessment



Source: Company Data, Team Estimates

Exhibit 17:
Structural Rigidity



Source: Company Data, Team Estimates

Revenues Evolution: Rebalancing for the AI & Computing Boom

As of FY24, TPRO reported €543M in consolidated revenues, rebounding from a transitional FY23 (€409.3M, -25.4% YoY) marked by severe destocking in the consumer market. The company is currently executing a strategic pivot from consumer-centric electronics toward high-growth infrastructure. TPRO estimates mid-single digit organic growth, supported by a gradual industry recovery and the structural ramp-up of AI-related demand.
Across its core segments, TPRO leverages its leadership in Vertical MEMS to capture shifting market dynamics. The Mobile (Smartphone/Tablet) segment was diluted to 49% in FY24 as the portfolio diversified. Despite a projected slight decline in mix to 46-48% for FY25E, this division is expected to benefit from the positive impact of Edge AI and the next generation of premium chipsets. Conversely, the Computing & Data Center subsegment (surging from ~20% in FY23 to 35% in FY24) is positioned as the primary growth engine, forecasted to reach 36-38% of the mix in FY25E. This expansion is fundamentally driven by massive investments in AI-driven data centers, where testing complexity increases significantly.
Finally, the Automotive & Industrial division (14% of FY24 sales) faces temporary cyclical headwinds, with a projected mix contraction to 11-13% in FY25E due to inventory normalisation. Despite these short-term pressures, TPRO's strategic positioning in advanced nodes (3nm and below) and the integration of the DIS segment consolidate its path toward the future.

Strategic Capex: Self-Funded Integration for AI & HBM

Technoprobe's capital expenditure strategy is a pillar of its competitive moat, characterized by a high degree of vertical integration. Despite the cyclical downturn in FY23, TPRO maintained a sustained investment cycle, with Capex focused on expanding its Vertical MEMS production capabilities. In FY24, Capex remained elevated to support the construction of the new production hub in Cernusco Lombardone and the expansion of cleanroom facilities, essential for the high-precision manufacturing required by sub-3nm chip architectures. This "invest-ahead-of-the-curve" approach has resulted in Capex/Sales ratio that exceeds industry peers, reflecting TPRO's commitment to internalizing the production of critical components, a strategy that secures supply chain resilience and protects proprietary manufacturing secrets.

The integration of the Device Interface Solutions (DIS) segment has added a new layer to the Capex profile, requiring targeted investments to harmonize Teradyne's former operations with TPRO's technological standards. Looking into FY25E, Capex is expected to stabilize as major infrastructure projects reach completion, shifting the focus toward R&D-driven laboratory equipment for Advanced Packaging and HBM (High Bandwidth Memory) testing. Supported by a robust Net Cash Position of >€600M, TPRO's Capex is entirely self-funded, allowing the company to aggressively pursue technological leadership without financial strain.

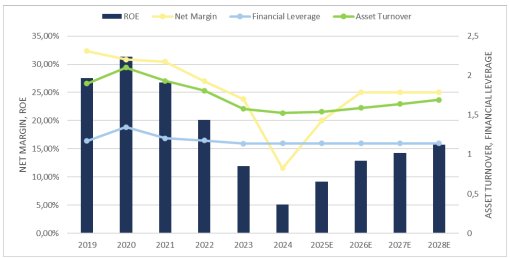
PPE Structure: A young asset base as a technological moat

Technoprobe employs a straight-line depreciation method, balancing technological obsolescence with asset durability. Looking at exhibit 16, our analysis of the average asset age yields a critical valuation metric: we obtained an average age of 4.1 years by scaling the accumulated depreciation (€212.4m, as of FY24) against the Annual Depreciation (€51.1m),. When compared to a weighted average useful life of 10.0 years, this confirms a "young" and technologically current asset base with significant remaining economic life.
Moreover, the €6.5m impairment related to Harbor and Microfabrica underscores management's commitment to high-efficiency assets capable of handling 3nm node complexity. The current PPE structure reveals that 13.5% of the total asset base consists of assets under construction (CIP), representing a massive "technological reserve" for AI-driven capacity expansion. This asset "freshness" minimizes the immediate need for maintenance CapEx. By keeping replacement costs low, Technoprobe can strategically allocate nearly its entire capital budget toward Growth CapEx (Cernusco hub and Taiwan expansion). This creates a superior return on invested capital (ROIC) profile, as capital is funneled into high-margin scaling rather than mere operational survival.

Fixed R&D: Investing for the Next Upcycle

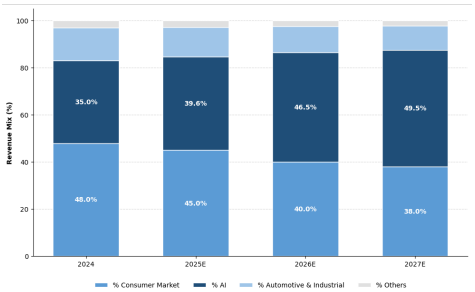
TPRO's R&D expenses are modeled as entirely fixed, reflecting a strategy that aims to sustain innovation regardless of market volatility. Maintaining high R&D intensity during demand contractions is crucial to preserve technological leadership and proprietary know-how. Even though this approach impacts short-term margins,as observed in FY23,it reinforces the company's long-term competitive positioning and ensures immediate readiness for the next technology upcycle.

Exhibit 18:
Dupont Analysis



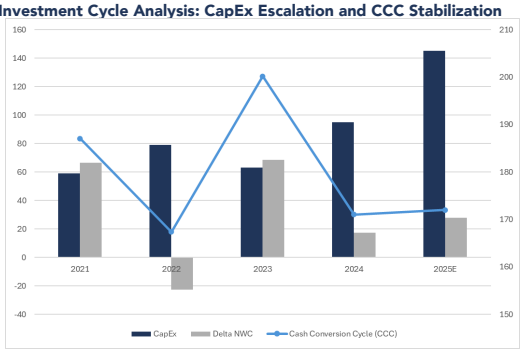
Source: Company Data, Team Estimates

Exhibit 19:
Projected Revenue Mix Evolution: The Pivot Toward AI Testing



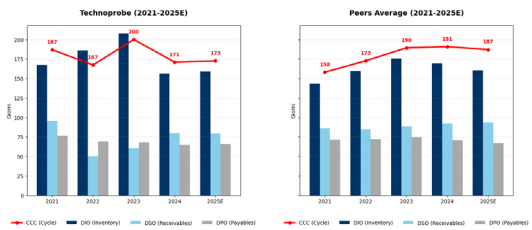
Source: Company Data, Team Estimates

Exhibit 19:
Investment Cycle Analysis: CapEx Escalation and CCC Stabilization



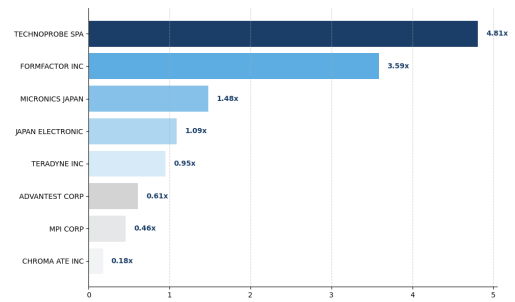
Source: Company Data, Team Estimates, Bloomberg

Exhibit 20:
CCC benchmark: Technoprobe vs peers average



Source: Company Data, Team Estimates, Bloomberg

Exhibit 21:
A peer comparison: Net cash/EBITDA



Source: Company Data, Team Estimates, Bloomberg

Technoprobe's Profitability

Technoprobe's ROE (5.1% in FY24) stands at a cyclical trough, reflecting the company's deliberate asset-heavy and unleveraged positioning ahead of the AI-driven growth phase. While the Net Margin (11.6%) remains sound, profitability is temporarily compressed by a high fixed-cost rigidity (~25%), as the company absorbs elevated D&A and R&D expenses to preserve its technological moat.

The main drag on returns is the depressed Asset Turnover (~40%), stemming from the recent intensive CapEX cycle (Cernusco hub and DIS acquisition), which has resulted in underutilisation of production capacity. However, this operating structure, combined with a conservative Equity Multiplier (1.14x), embeds a high Degree of Operating Leverage (~3.0). This configuration acts as a "coiled spring": with the fixed cost base already in place, the expected AI-driven volume growth should translate into disproportionate operating and net income growth. As capacity utilization and Asset Turnover normalize, operating leverage is expected to drive margin expansion, allowing ROE to recover toward the 15–20% range over the medium term, without reliance on financial leverage.

Cash flow generation and earnings quality

Technoprobe exhibits a high quality of earnings, characterized by a robust correlation between EBITDA and Cash Flow from Operations (CFO). Historically, the company has maintained a cash conversion ratio, defined as CFO/EBOTDA, close to 70%. This metric suggests that reported profits are not inflated by aggressive accounting accruals but are supported by timely cash inflows.

This operational efficiency translates into a solid FCFF profile, despite the capital-intensive nature of the current 3nm node expansion. While the company's reinvestment rate has accelerated to support the AI-related capacity, the strength of its unlevered cash flow highlights a self-sustaining growth model.

Solvency & Capital Allocation for the "Next Wave"

Management has signalled an extraordinary plan to boost CapEx expenditures for the 2026-2027 up to 200-250 million, aimed at expanding the capacity to intercept the "inference calculation" wave in data centers. Technoprobe's fortress balance sheet, boasting a net cash position exceeding €600M, serves as a strategic enabler. This solvency is structurally highlighted by a solid debt profile: with a conservative equity ultiplier of 1.14x and negligible gross financial debt, the company operates with virtually no leverage dependency. This unleveraged capital structure not only immunizes the bottom line against interest rate volatility and financing dependencies. This liquidity buffer allows the company to potentially fully self-fund this aggressive capacity expansion ahead of the demand curve without leveraging the balance sheet, maintaining financial flexibility.

Cash Conversion Cycle and NWC

Technoprobe's working capital management is characterized by a structurally high cash conversion cycle (CCC), largely driven by an intensive days inventory outstanding (DIO) profile. The cycle experienced a significant peak in 2023, reaching 200 days as inventory levels swelled to over 207 days, which directly contributed to substantial cash absorption as evidenced by the positive delta NWC in that period. While DSO showed marked volatility, dropping sharply in 2022 before rebounding, the inherent weight of inventory remains the primary catalyst for fluctuations in NWC. In comparison to peers, Technoprobe maintains a distinct profile where inventory, rather than receivables, serves as the main driver of capital lock-up. This reliance on high stock levels to support operations necessitates disciplined supply chain management to mitigate liquidity risks. Consequently, historical trends underscore a persistent challenge in balancing operational readiness vwith cash flow efficiency regardless of short-term estimates.

Strategic Re-rating: Enhancing Revenue Quality through the AI Segment

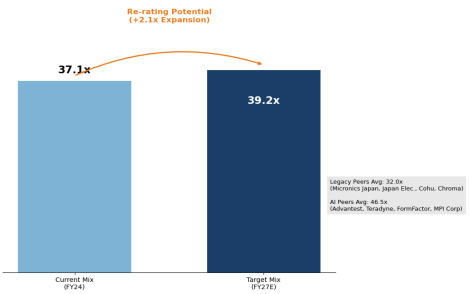
Technoprobe is undergoing a significant structural revenue shift, strategically reorienting its business mix from cyclical consumer markets toward the high-growth artificial intelligence sector. The AI segment is projected to grow from 35.0% of total revenues in 2024 to 49.5% by 2027E, becoming the dominant revenue contributor and surpassing the declining consumer segment (48.0% to 38.0%). This transition is strategically vital, as AI-driven testing is characterized by higher technological complexity, superior margins, and exposure to long-term secular growth trends, unlike the more cyclical and cost-sensitive consumer and automotive end-markets. Consequently, we expect this improving revenue quality to drive a fundamental re-rating of Technoprobe's valuation multiple, aligning it closer to pure-play AI testing peers as the company's earnings profile becomes more structural and less cyclical.

Exhibit 22:
Peersi Financial Analysis

PEERS				
Sectors	Company	P/E Forward	CAGR:2FY	EV/EBIT 2027E
Legacy Group	COHU INC	47,06	16,50%	13,19
	MICRONICS JAPAN	25,89	13%	16,47
	JAPAN ELECTRONIC	16,92	11,10%	10,1
	CHROMA ATE	38,28	25%	26,59
	Average	**32,0375**	**16%**	16,5875
Advanced Tester (AI)	TERADYNE	47,23	20,60%	30,65
	MPI	60,81	36,30%	28,09
	FORMAFACTOR	45,06	7,70%	31,05
	ADVANTEST	47,43	21,50%	36,69
	Average	**50,1325**	**21,53%**	**31,62**
	TECHNOPROBE	**62,5**	**21%**	**31,05**

***Source: Company Data, Team Estimates**, Bloomberg*

Exhibit 23:
Valuaition Multiple Re-rating: Potential for P/E Expansion by FY27



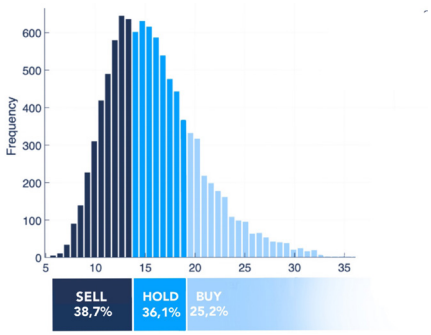
Source: Company Data, Team Estimates, Bloomberg

Exhibit 24:
DCF Sensitivity Analysis

WACC \ g	2,0%	2,5%	3,0%	3,5%	4,0%
6,65%	17,1	18,6	20,6	23,2	26,8
7,15%	15,4	**16,6**	**18,1**	**20,0**	22,5
7,65%	14,0	**15,0**	**16,1**	**17,6**	19,4
8,15%	12,8	**13,6**	**14,5**	**15,7**	17,1
9,65%	10,2	10,7	11,2	11,8	12,5

Source: Company Data, Team Estimates

Exhibit 25:
DCF MonteCarlo Analysis



Source: Company Data, Team Estimates

Relative Valuation: Structural Expansion & 2027 Multiple Analysis

To derive a robust target price for Technoprobe, we employed a forward P/E valuation method anchored to FY2027 estimates. We adopted a strategy to capture the structural re-rating driven by the company's revenue evolution: as Technoprobe shifts its revenue mix from cyclical consumer and automotive testing toward the high-margin, high-growth artificial Intelligence market, we argue that its valuation multiple must fundamentally expand to reflect this superior quality of earnings.

To quantify this shift, we determined a target multiple by applying cluster-specific P/E ratios to the projected 2027 revenue mix. From our peer universe (Appendix 07), we weighted the average valuation of legacy peers (32.0x), and advanced testing peers (46.5x) against a projected 2027 sales split of 50.5% and 49.5%, respectively. This approach results in a fundamental re-rated multiple of 39.2x (Exhibit 23). We adopted this metric as our target P/E to ensure the valuation is strictly grounded in peer fundamentals and current growth-to-value correlations. Applying this multiple (39.72) to the FY2027 Consensus EPS estimate of €0.35 results directly in a Target Price of €13.90. We recognize that this fundamental-only approach remains inherently conservative; it acts as a valuation floor by excluding the significant "scarcity premium" and momentum that the market attributes to Technoprobe.

Valuation Methodology: Multi-Stage DCF & Target Weighting

Our valuation for Technoprobe is anchored by a two-stage DCF model projected through 2034. For the initial high-growth phase (2025–2029), we project aggressive revenue expansion (peaking at 30% in 2026) (Appendix 09) driven by heavy Capex investment in AI, HBM testing, and TPEG™ adoption. As the market enters a mature cycle (2030–2034), we transition to a medium-growth trajectory, with revenue tapering from 9% to 4% as capital intensity normalizes.

Post-2034, we apply a terminal growth rate of 3.0%, reflecting our conviction that semiconductor testing intensity will structurally outperform global GDP. This premium is grounded in the "irreversible complexity" of Moore's Law: as transistor density doubles every two years, physical contact targets shrink to microscopic scales (<50μm), making standard testing obsolete and requiring Technoprobe's proprietary TPEG™ MEMS and DIS interfaces to physically access the silicon. Because this gap between chip density and testing precision widens with every generation independent of economic cycles, we assume Technoprobe retains pricing power aligned with global inflation (2.0%) plus a 1.0% real growth "complexity premium."

To arrive at our final valuation, we utilized a weighted average approach: 80% assigned to our DCF results and 20% to a Comparable Analysis. Based on the current share price data and these weighted inputs, we derive a final target price of €15.66.

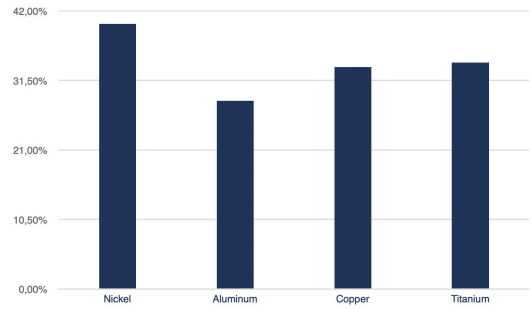
DCF Statistical Robustness & Valuation Calibration

This sensitivity matrix (Exhibit 24) confirms the structural robustness of our DCF valuation, demonstrating that the base case of €16.1 sits securely within a high-conviction range that withstands significant fluctuations in both discount rates and terminal growth assumptions Based on the Monte Carlo simulation (Appendix 06) of 10,000 iterations, a target price of €16.1 is statistically well-supported as it aligns closely with the distribution's expected value of €15.98. Given the current "Hold" range (defined as €14.0–€18.5), our target sits comfortably within the highest-density region of the curve, where the probability of occurrence is greatest. From an economic perspective, the 36.1% probability of a "Hold" outcome suggests that while the growth prospects are strong, the valuation is currently fairly priced. The right-skewed tail indicates some "moonshot" potential, but staying at €16.1 accounts for the 38.7% downside risk (Sell) without overpaying for optimistic terminal growth assumptions.

Exhibit 26:
Discounted Cash Flow at a glance

			High Growth Projection Period				Medium Growth Projection Period				
DCF (€M)	**2024A**	**2025E**	**2026E**	**2027E**	**2028E**	**2029E**	**2030E**	**2031E**	**2032E**	**2033E**	**2034E**
EBIT	67	67	278	353	417	490	573	659	725	790	861
% Tax rate	28%	24%	24%	24%	24%	24%	24%	24%	24%	24%	24%
NOPAT	48	51	211	268	317	372	435	501	551	600	654
+D&A	70	69	82	75	78	91	107	123	135	147	161
- Δ Working Capital	16	28	29	32	33	26	30	26	28	21	22
CF From operations	125	92	264	311	362	437	512	598	658	726	793
- Net CapEx	94	63	147	122	133	97	122	140	154	168	184
FCF to the firm	8	29	118	189	229	340	390	458	504	558	609
% of EBIT	12%	43%	42%	54%	55%	69%	68%	69%	70%	71%	71%
PV of FCFF			109	163	183	253	270	294	300	310	313
				707				1486			

Exhibit 27:
Raw Materials Annualized Price Volatility Over Last 10 Years

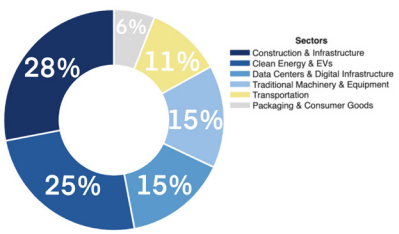


Source: Deutsche Borse, Company Data, Team Estimates

Exhibit 28:
Projected Industrial Metals Supply by Region (2026)

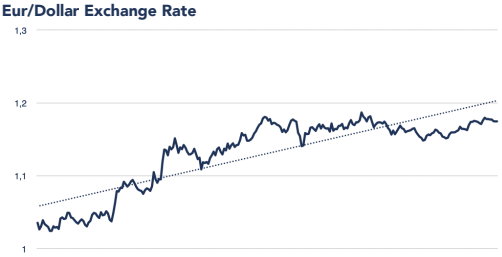
Source: Company Data, S&P Global

Exhibit 29:
Projected Industrial Metals Demand by Sector (2026)



Source: Team Estimates, Investing.com

Exhibit 30:
Eur/Dollar Exchange Rate



Source: Team Estimates, Investing.com

Exhibit 31:
H1 2025 Customer Concentrated Revenue

Source: Company Data, 1

Raw Materials Price Risk - Risk 1

Approximately 30% of COGS is represented by industrial commodities such as nickel alloys, aluminum, copper and titanium (Appendix 13), which are characterized by significant annualized price volatility recorded over recent years (Exhibit 27). These metals are critical for key elements such as probe needles, MEMS structures, heat sinks and electrical pathways. Supply is strongly concentrated in geopolitically sensitive regions such as China, Indonesia and South America (Exhibit 28), while demand is increasingly driven by data centers for AI applications, Electric Vehicles and renewable energy, in addition to more traditional but cyclical demand sources, creating persistent upward pressure (Exhibit 29). A shock in input prices could dangerously increase COGS, compressing Technoprobe's EBITDA as a consequence in the short-term, before any pricing response (Appendix 15) .
Mitigation: The main mitigation factor is represented by Technoprobe's estimated cost pass-through rate of 75% over 12-18 months, which will be furtherly favoured by shifting the product mix towards higher value-added solutions like HBM card, allowing for greater pricing power. Moreover, the company employs multiple proactive strategies: one consists of building strategic inventory buffers when prices are favorable to protect against sudden spikes, which resulted successful while hedging Palladium's rise in 2022. Also, its push towards vertical integration reduces reliance on external suppliers. These efforts are supported by long-term supplier agreements designed to lock in stability whenever possible.

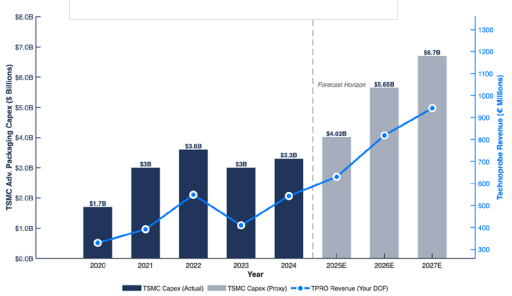
Forex Risk - Risk 2

Technoprobe has a significant structural currency mismatch: about 90% of revenues are in USD, while a large portion of its cost base is in EUR. This exposes the company to EUR/USD fluctuations, in particular to Euro strengthening, compressing as a consequence EUR-reported margins. The risk materialized sharply in H1 2025, resulting in a €35.9 million FX loss, of which €30.7 million unrealized, primarily due to USD's depreciation against the Euro (Exhibit 30). While Technoprobe employs financial hedging strategies, balance-sheet data show derivative financial assets of only €0.2 million at H1 2025, a minimal amount compared to the scale of USD revenues and the €35.9 million FX loss recorded in the period. This indicates that the company's hedging program provides only limited protection against currency fluctuations, leaving a substantial portion of USD exposure unhedged. (Appendix 18 & Appendix 19)
Mitigation: Despite the apparent insufficiency of the hedging program, over the longer term, the company is gradually attempting to diversify its manufacturing footprint outside the Eurozone, which should structurally reduce the EUR-weighted cost base and exposure to EUR appreciation against the USD as a natural consequence. In general, all treasury and risk management activities are centralized, ensuring a coordinated and disciplined response to currency movements.reduce the EUR-weighted cost base.

Customer Concentration Risk - Risk 3

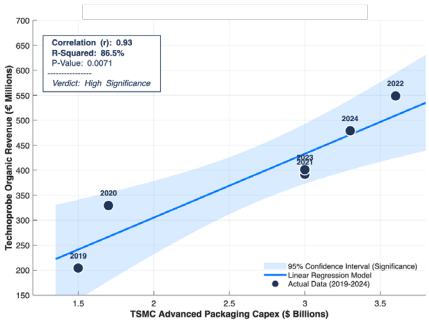
Revenue is heavily concentrated, with the top two clients accounting for 48.8% of H1 2025 Sales, and Top 5 clients accounting for approximately 70% of total Revenues (Exhibit 31), likely being TSMC, Samsung, Intel, STMicroelectronics and Sony. This creates vulnerability to external factors such as order reductions, choices to acquire from competitors or insourcing efforts by any major client, potentially undermining an extremely significant portion of revenues as a consequence. This also leads to Technoprobe's growth being tied to the capital expenditure cycles of its customers in specific end-markets. Looking at the half-year relation of June 2025, revenues stemming from the first client increased from 17% in H1 2024 to 32% in H1 2025. However, Technoprobe is actively trying to diversify both its customer base and its market reach. As a matter of fact, a slight increase in revenue base from H1 2024 to H1 2025 has been positively noticed. This is driven by success in high-growth segments like AI and High Bandwidth Memory (HBM), which has already attracted new key clients.
Mitigation: Although specific disclosures regarding formal multi-year contracts remain limited due to industrial secrecy, Technoprobe's operational stability is underpinned by the "roadmap inclusion" model. This mechanism integrates the company into the developmental architecture of critical 3nm and 2nm nodes years before mass production, creating a "de facto" multi-year commitment. Once Technoprobe's Vertical MEMS technology is validated for a specific node, the switching costs for foundries become prohibitive, effectively functioning as an implicit long-term agreement. Consequently, this deep technical integration mitigates the risks of high customer concentration by transforming Technoprobe from a standard vendor into an irreplaceable strategic partner.

Exhibit 32:
TSMC Advanced Packaging Capex vs Technoprobe Revenues



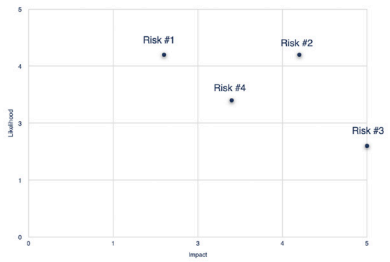
Source: Company Data, Team Estimtates

Exhibit 33:
Statistical Robustness: TSMC Capex vs Technoprobe Revenue



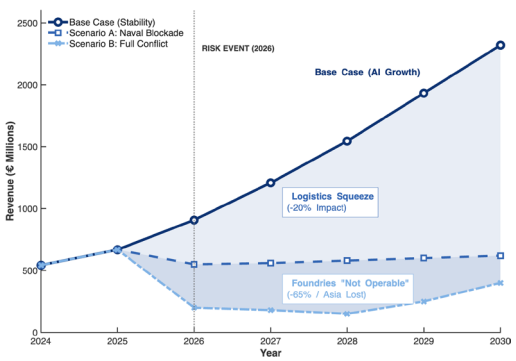
Source: Company Data

Exhibit 34:
Risk Matrix



Source: Company Data, Team Estimtates

Exhibit 35:
Geopolitical Risk Assesment: China-Tawain Degeneration Impact



Source: Company Data, Team Estimates

Structural Symbiosis & Investment Risk: The "Synchronous Coupling" Trap

Exhibit 32 illustrates the structural correlation between TSMC's Advanced Packaging capital expenditure and Technoprobe's top-line performance, a mutual dependency formally validated in late 2024 when Technoprobe received TSMC's "Excellent Performance Award" for its critical integration into advanced 3nm and 2nm nodes. While this partnership secures vital yield assurance for high-power AI silicon via Technoprobe's proprietary TPEG™ MEMS technology, an econometric analysis of the dataset, strictly sanitized to exclude inorganic noise from DIS and Harbor acquisitions, reveals a perilous "Synchronous Coupling." The organic regression confirms a high coefficient of determination (R-squared approx. 86.5%, $p<0.01$), while time-lag tests (t-1) were statistically rejected (R-squared dropping to approx. 35%), proving that Technoprobe's revenue does not trail but moves in lockstep with TSMC's capital deployment. However, this immediate realization of value eliminates any operational buffer: as witnessed in FY23, a moderation in client spending triggered a -25.4% revenue contraction, demonstrating that the company is hyper-sensitive to investment deceleration. Furthermore, as TSMC expands ("goes up"), this dependency exacerbates "Success Vulnerability"; with the top two clients already representing 48.8% of sales, Technoprobe faces heightened exposure to Taiwan-China geopolitical tensions and the looming threat of insourcing, where major clients may internalize testing to capture margins as volumes surge

Execution Risk on Innovation and M&A Integration - Risk 4

The semiconductor testing market requires continuous and successful innovation. Technoprobe's R&D intensity was 8.3% of sales in H1 2025, consisting of about €26.9 million. Failure to execute on key innovation fronts risks leaving crucial market share to competitors like FormFactor and Micronics Japan. Another potential risk source arises from M&A integration, particularly the ongoing restructuring of DIS Tech America Inc. This process has already triggered a €4.7 million provision for onerous contracts and risks, with assets held for sale, directly impacting the P&L and proving the cost of integration challenges. Moreover, the financial risk of acquisitions is exemplified by the Yee Wei Inc. minority buyout, valued at approximately $30 million and settled partly with 441,176 newly issued Technoprobe shares. This transaction introduces a direct share dilution risk, likely to materialize if Yee Wei's advanced packaging capabilities do not generate projected returns.
Mitigation: R&D investment remains high and targeted, with €54.4 million spent in 2024. Cost discipline is operational, not just strategic, as shown by the definitive exit from loss-making Harbour Electronics manufacturing activities located in the US. The strategic partnership with Advantest, cemented by the sale of a 2.5% stake from T-PLUS, is a calculated move to secure a critical distribution channel and align with a key industry player. Internally, the company emphasizes vertical integration, producing over 85% of its probe cards internally to control its technology roadmap and supply chain. Finally, the alignment of management incentives is structural: the 2021-2025 Long-Term Incentive Plan explicitly ties a significant portion of executive compensation to multi-year EBITDA and Total Shareholder Return targets, creating a direct financial stake in successful long-term execution and integration.

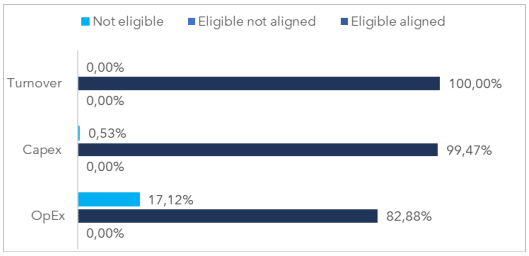
Geopolitical Stress Test

Geopolitical tension in the Taiwan Strait represents a structural "tail risk" rather than a cyclical one. We analyze this because Technoprobe's "AI Growth" thesis is inextricably linked to this region, with an expectation of ~46% of revenue for the next years derived from Asia for next years and a dependency on Taiwan's advanced foundries (TSMC) for leading-edge probe cards.
Exhibts 35 performs a quantitative stress test to measure the "asymmetry" of this exposure. It contrasts the consensus Base Case (Deep Blue), where stability allows AI demand to drive revenue to €2.3bn by 2030, against two specific degeneration scenarios modeled on supply chain fragility. Scenario A: The "Grey Zone" Blockade (Mid Blue): Models a "Logistics Freeze" where non-kinetic customs friction prevents physical delivery, causing a ~20% revenue drop due to inventory obsolescence and inability to recognize revenue. Scenario B: Full Conflict (Light Blue): Models a "Market Erasure" event where fabs become "not operable." This assumes a structural loss of the entire Asian market (~65%), shrinking the company to its US/EU "Safe Haven" footprint.

Global Diversification to face geopolitical risk

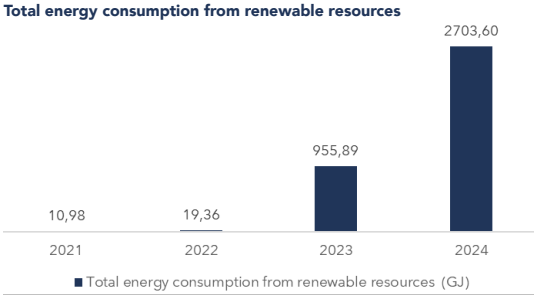
As said, geopolitical tension in the Taiwan Strait represents a structural "tail risk" for Technoprobe. This "asset concentration" risk is being actively mitigated. For example, TSMC's global diversification strategy, which involves massive investments in the US, Europe and Japan. While leading-edge capacity remains concentrated in Taiwan, TSMC's expansion into Arizona (advanced nodes) and Dresden (automotive) allows Technoprobe to decentralize its support infrastructure and acting as a vital mitigant for Technoprobe's geographical risk by decentralizing production away from the Taiwan Strait. By expanding beyond Taiwan, where 90% of wafer capacity was historically concentrated, TSMC structurally reduces the "asset concentration" risk for its primary suppliers. This shift allows Technoprobe to safeguard a part of its revenue exposure to Asia while leveraging its Italian headquarters and Fremont facility to provide localized support for these new global hubs. Consequently, this symbiosis transforms a regional "tail risk" into a diversified global opportunity.

Exhibit 36:
Technoprobe EU Taxonomy Allignment



Source: Company Data, Team Estimates, Technoprobe Sustenability Statement

Exhibit 37:
Total energy consumption from renewable resources



Source: Company Data, Team Estimates, Technoprobe Sustenability Statement

Exhibit 38:
ESG Maturity Assessment Table

Level	Stage Name	Definition (From Source)	Implied Data Quality
1	Initial efforts	Early-stage initiatives with limited scope and low level of formalization.	Low / Informal
2	Basic	Fundamental policies in place, but limited implementation and weak quantitative disclosure.	Weak / Incomplete
3	Industry standard	Practices aligned with common sector standards and regulatory expectations.	Standardized
4	Above average	Well-developed policies supported by measurable actions and higher transparency compared to peers.	High / Measurable
5	Leader	Best-in-class performance with comprehensive strategies, robust quantitative indicators and high level of transparency.	Robust / Transparent

Source: Company Data, Team Estimates

Exhibit 39:
ESG grade Technoprobe

E	S	G	
40%	*30%*	*30%*	*100%*
2	3.5	3	**2.75**

Source: Company Data, Team Estimates

Taxonomy Eligibility Overview

In accordance with Regulation (EU) 2020/852, Technoprobe's assessment for the 2024 fiscal year demonstrates a high degree of Taxonomy-eligibility, reflecting the intrinsic value of its core operations within the semiconductor value chain. Specifically, 100% of Turnover and 99.47% of Capital Expenditure (CapEx) are classified as eligible, confirming that the Group's primary activity, the design and manufacture of probe cards, falls within the economic sectors identified by the European Commission as critical for enabling climate change mitigation (likely categorised under Activtity 3.6: Manufacture of other low carbon technologies). However, the current classification of these activities as 'Eligible but not aligned' reflects a prudent approach to the rigorous Technical Screening Criteria (TSC). While the nature of the business supports the low-carbon transition, the specific documentation required to validate the 'Substantial Contribution' and 'Do No Significant Harm' (DNSH) clauses was not fully finalized for this reporting period. Meanwhile, the 17.12% of OpEx identified as 'Not eligible' pertains strictly to administrative and non-industrial operational costs that fall outside the Taxonomy's scope, delineating a clear boundary between core manufacturing activities and general corporate overhead.

Technoprobe's Path to Climate Neutrality: Scaling On-Site Solar Capacity

Technoprobe's sustainability data is best understood as the direct execution of its "Energy Transition" strategy, a core pillar of the company's ESG roadmap aimed at achieving Climate Neutrality. To reduce its carbon footprint (specifically Scope 2 emissions (indirect emissions from purchased electricity)). Technoprobe committed to shifting from grid reliance to massive self-generated renewable power at its primary industrial sites.
This strategic pivot is empirically demonstrated in your chart. The data captures the precise moment Technoprobe's proprietary photovoltaic infrastructure came online:

- The Pivot Point (2023): The sudden exponential jump to 955,89 GJ marks the activation of the solar plants at the Cernusco Lombardone headquarters, a project explicitly detailed in their Consolidated Non-Financial Statement.
- The Scale-Up (2024): The subsequent tripling to 2.703,60 GJ in 2024 reflects the first full year of operational capacity, validating the company's ability to meet its published targets for renewable self-consumption.

Moving forward, Technoprobe's 2024 Sustainability Statement (aligned with the new European ESRS standards) indicates this is not a one-off spike but a permanent structural change, with further investments planned to maintain this lower-emission operational model.

Technoprobe: Green Hopes, Red Flags

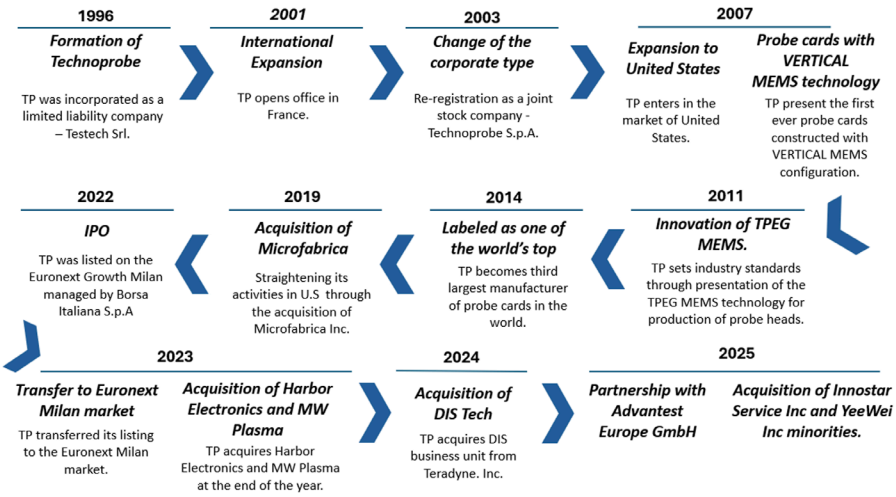
Technoprobe occupies a distinct "middle ground" (Appendix 14) in the semiconductor test sector's ESG landscape, effectively functioning as a "Social Leader" while trailing as an "Environmental Laggard." With a final weighted score of 2.75, the firm outperforms static peers like FormFactor and JEM but remains significantly behind strategic leaders like Chroma ATE (3.90) and MJC (3.15). The company's valuation is primarily anchored by its Social performance (3.15), where it ties for first place; its industry-leading low injury rate (1.65) and structured corporate welfare programs position it as a "safe pair of hands" in a sector plagued by talent shortages. However, this strength is counterbalanced by a critical weakness in the Environmental pillar, which carries the highest weight (40%) in our scoring model. Scoring just 2.0, Technoprobe lacks the "Green Revenue" engines of Chroma or the circular economy initiatives of MJC, with renewable energy usage languishing at 1.5%. This creates a clear strategic imperative for the future: as major IDMs (Integrated Device Manufacturers) aggressively audit Scope 3 emissions, Technoprobe's "carbon inaction" risks becoming a liability. To evolve from a compliant vendor to a preferred partner, the company must urgently formalize a climate transition plan, moving beyond social safety to environmental sustainability.

Exhibit 40:
ESG Grade Table, Technoprobe vs Peers

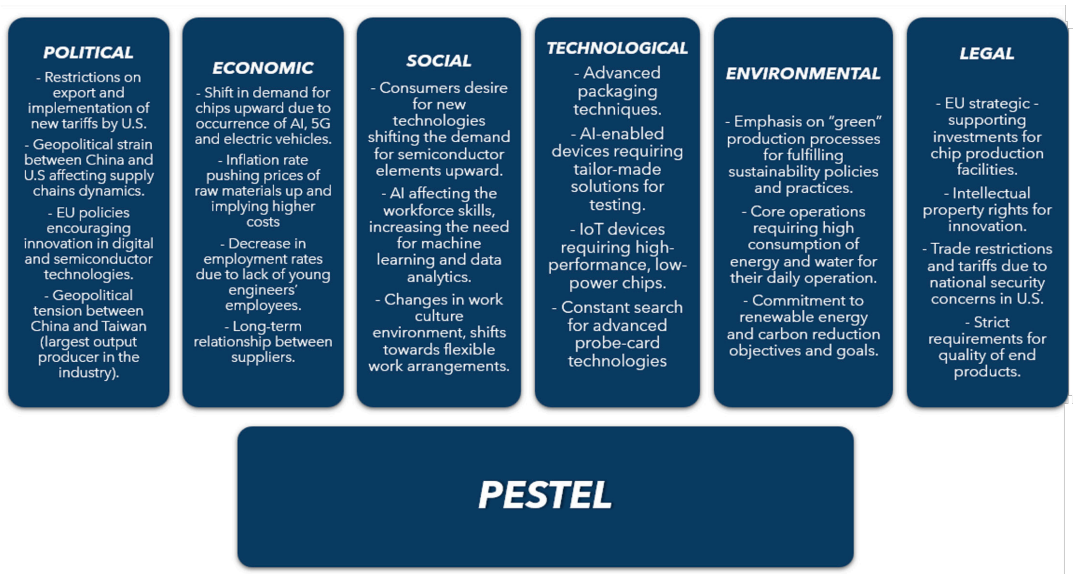
Company	Environmental (Weight: 40%)	Social (Weight: 30%)	Governance (Weight: 30%)	Final Weighted Score	Strategic Status
Chroma ATE Inc.	4.5	3.0	4.0	3.90	Leader (Green Revenue Moat)
Micronics Japan (MJC)	3.0	3.5	3.0	3.15	Runner Up (Human Capital Focus)
Technoprobe S.p.A.	**2.0**	**3.5**	**3.0**	**2.75**	**Mid-Tier (Strong Social / Weak Env)**
Japan Elec. Materials	1.5	1.5	2.0	1.65	Initial Efforts
FormFactor	1.0	1.5	1.5	1.30	Laggard

Source: Company Data, Team Estimates

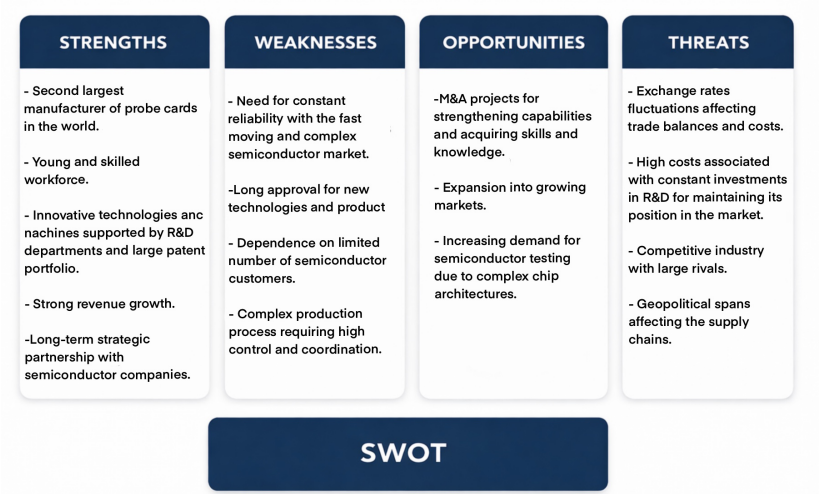
Appendix 01 - Technoprobe Timeline



Appendix 02 - Pestel



Appendix 03 - SWOT



Appendix 04 - Income Statement

(in € Millions)	2019	2020	2021	2022	2023	2024	2025E	2026E	2027E	2028E	2029E	2030E	2031E	2032E	2033E	2034E
Revenue	**172,5**	**329,5**	**391,7**	**548,9**	**409,3**	**543,2**	**627**	**819,7**	**941**	**1111,5**	**1305,9**	**1528,2**	**1759,2**	**1933**	**2106,7**	**2296,1**
% Revenue growth	-	*91,00%*	*18,90%*	*40,10%*	*-25,40%*	*32,70%*	*15,50%*	*30,00%*	*14,80%*	*18,10%*	*17,50%*	*17,00%*	*15,10%*	*9,90%*	*9,00%*	*9,00%*
Cost of revenue	-81,3	-126,1	-157	-216,1	-209,9	-319,7	-321,5	-409,8	-470,5	-533,5	-613,8	-718,3	-809,2	-889,2	-969,1	-1033,2
Gross profit	**91,2**	**203,4**	**234,7**	**332,8**	**199,3**	**223,4**	**309**	**409,9**	**470,5**	**578**	**692,1**	**809,9**	**950**	**1043,8**	**1137,6**	**1262,9**
Operating expenses	-33,5	-61	-84,8	-124,3	-119,5	-156,3	0,49	0,5	0,5	-294,5	-339,5	-389,7	-439,8	-483,3	-516,1	-551,1
of which R&D Expenses	-14	-20,6	-33,7	-56,4	-56,8	-63,4	-170,2	-221,3	-254,1	-122,3	-143,6	-168,1	-193,5	-212,6	-231,7	-252,6
of which SG&A & Other	-19,5	-40,4	-51,1	-67,9	-62,7	-92,9	-75,7	-98,4	-112,9	-172,2	-195,9	-221,6	-246,3	-270,7	-284,4	-298,5
Operating profit	**57,7**	**142,4**	**149,9**	**208,4**	**79,8**	**67,1**	**138,8**	**188,6**	**216,4**	**283,5**	**352,6**	**420,2**	**510,2**	**560,5**	**621,5**	**711,8**
Other income (expenses), net	-3,3	-12,8	-4,5	-4,2	1,9	2,5	0,22	0,23	0,23	0	0	0	0	0	0	0
Financial income	0,3	0,2	0,1	1,2	8,6	17,1	22	27,5	32	43	53,5	68,5	83,8	99	119,5	145
Financial expenses	-0,1	-0,2	-0,2	-0,2	-0,3	-1,6	160,8	216,1	248,4	-3	-3,5	-3,5	-3,8	-4	-4,5	-5
Foreign exchange gains (losses)	0,5	-5	7,1	1,9	-4,8	11,9	-38,6	-51,9	-59,6	0	0	0	0	0	0	0
Profit before tax	**55,1**	**124,6**	**152,4**	**207,2**	**85,2**	**97**	**122,2**	**164,2**	**188,8**	**323,5**	**402,6**	**485,2**	**590,2**	**655,5**	**736,5**	**851,8**
Income tax expense	-8,2	-23	-33,1	-59	12,1	-34,2	-36,4	-47,2	-56,4	-77,6	-96,6	-116,4	-141,6	-157,3	-176,8	-204,4
Profit for the year (Net Profit)	**46,9**	**101,6**	**119,3**	**148,2**	**97,4**	**62,8**	**85,8**	**117**	**132,4**	**245,9**	**306**	**368,8**	**448,6**	**498,2**	**559,7**	**647,4**

Appendix 05 - Balance Sheet

Balance Sheet (in € Millions)	2019	2020	2021	2022	2023	2024	2025E	2026E	2027E	2028E	2029E	2030E	2031E	2032E	2033E	2034E
Intangibles and Goodwill	16.771	15.066	16.430	21.093	43.320	109.255	126	164	197	230	258	281	301	319	335	348
Property, Plant & Equipment	92.169	127.250	169.198	209.736	252.278	295.147	341	443	532	622	697	759	813	861	905	941
Equity accounted investees	378	491	835	1.021	1.388	1.083	1,2	2	2	2	2,6	3	3	3	3,3	4
Net Fixed Assets	**109.318**	**142.807**	**186.463**	**231.850**	**296.986**	**405.485**	**468**	**609**	**731**	**855**	**958**	**1.043**	**1.117**	**1.184**	**1.243**	**1.292**
Accounts Receivable	46.310	80.280	102.848	75.418	67.829	118.803	137	178	214	251	281	306	327	347	364	379
Accounts Payable	-17.368	-27.332	-32.782	-40.858	-38.989	-56.904	-58	-74	-87	-102	-114	-124	-133	-141	-148	-154
Inventory	22.970	34.768	71.901	110.387	119.030	136.759	140	178	210	245	275	299	320	339	356	370
Other current assets/(liabilities) net	-12.194	-29.436	-17.196	-42.813	22.853	-10.415	-12	-16	-19	-22	-25	-27	-29	-30	-32	-33
Net Working Capital	**39.718**	**58.280**	**124.771**	**102.134**	**170.723**	**188.243**	**207**	**267**	**318**	**372**	**416**	**454**	**485**	**514**	**540**	**562**
Other non-operating assets	590	1.659	338	-2.141	-1.178	-12.285	-14,2	-18	-22	-26	-29	-32	-34	-36	-37,6	-39
Capital Employed	**149.626**	**202.746**	**311.572**	**331.843**	**466.531**	**581.443**	**661**	**857**	**1.026**	**1.201**	**1.345**	**1.465**	**1.568**	**1.662**	**1.746**	**1.815**
Owners of the Parent Company	238.492	322.039	443.750	735.936	815.772	1.237.553	1.353	1.502	1.681	1.890	2.125	2.383	2.661	2.958	3.272	3.602
Minority interests	1.555	2.185	2.533	1.039	1.528	-376	0	0	0	-0,4	0	0	0	-0,4	0	0
Total Equity	**240.047**	**324.224**	**446.283**	**736.975**	**817.300**	**1.237.177**	**1.353**	**1.502**	**1.680**	**1.890**	**2.125**	**2.383**	**2.661**	**2.957**	**3.272**	**3.602**
Medium/long term financial debt	1.970	6.005	5.516	5.847	10.392	13.843	16	21	25	29	33	36	38	40	43	44
Short term financial debt	543	31.181	6.659	2.352	3.135	5.540	6	8	10	12	13	14	15	16	17	18
Financial assets and derivatives	-1.101	-368	-132	-2.300	-2.496	-8.740	-10,1	-13	-16	-18	-20,6	-23	-24	-26	-26,8	-28
Cash and cash equivalent	-91.833	-158.296	-146.754	-411.031	-361.800	-666.377	-704	-661	-674	-712	-805	-945	-1.122	-1.326	-1.558	-1.821
Net Financial Position	**-90.421**	**-121.478**	**-134.711**	**-405.132**	**-350.769**	**-655.734**	**-692**	**-645**	**-654**	**-689**	**-780**	**-918**	**-1.093**	**-1.295**	**-1.526**	**-1.787**
Total Funds	**149.626**	**202.746**	**311.572**	**331.843**	**466.531**	**581.443**	**661**	**857**	**1.026**	**1.201**	**1.345**	**1.465**	**1.568**	**1.662**	**1.746**	**1.815**

Appendix 06 - WACC

Cost of Equity (Ke)	8.32%	Capital Asset Pricing Model (Rf + β * ERP)
Risk-free rate (Rf)	3.98%	Anchored to the 10-year Italian BTP yield
Market Beta (β)	**0.904**	Computed via OLS regression of TPRO's daily excess returns against a revenue-weighted blended market excess return
Market Premium	**4.8%**	Derived as a geographic weighted average of regional Equity Risk Premiums based on TPRO's revenue exposure
Cost of Debt (Kd)	3,50%	10 Year Bund plus Italian Credit Spread
Tax Rate	24%	Derived from historical Technoprobe's tax rates
E/(D+E)	88%	Derived from company data
D/(D+E)	12%	
WACC	**7.70%**	Final Weighted Average Cost of Capital calculation

Country	Weight	ERP	Weighted contribution (w×ERP)
USA	0,461	0,0433	0,01996
Taiwan	0,304	0,0513	0,0156
South Korea	0,07	0,0499	0,00349
Europe	0,049	0,0513	0,0025137
China	0,047	0,0527	0,00248
Japan	0,035	0,0527	0,00184
Italy	0,022	0,0726	0,0016
Singapore	0,012	0,0433	0,00052
Blended ERP			**0,0480037**

Cost of Equity

The cost of equity is determined by applying the Capital Asset Pricing Model (CAPM). Although Fama-French 3-factor and 5-factor models were tested, the CAPM was preferred for its reliability and to avoid overfitting: while some factors (CMA) showed statistical significance, all other factors turned out to be insignificant. Our framework utilizes a blended Equity Risk Premium (ERP) of 4.8%, calculated by weighting regional premiums according to Technoprobe's specific geographic revenue exposure. This resulted in a Cost of Equity of 8.32%, calculated as: Ke=Rf + Bm*(ERPblended).

Risk Free Rate

The Risk-Free Rate of 3.98% is anchored to the 10-year Italian Government Bond (BTP) yield. We used this approach as it reflects the sovereign risk environment of the company's primary listing (Borsa Italiana).

Market Beta

The Market Beta (0.904) was derived from an OLS regression of Technoprobe's daily excess returns against a blended market excess return. This benchmark was constructed by weighting regional equity indices (e.g., S&P 500, TWII) according to the company's geographic revenue split, ensuring that the systematic risk is measured on a market portfolio that replicates its geographic exposure.

WACC

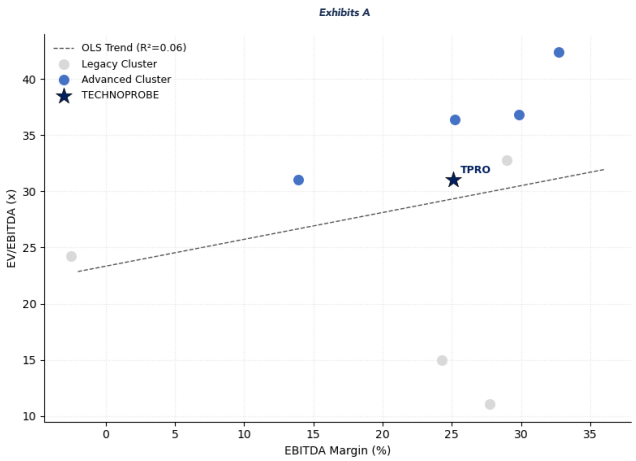
The resulting WACC after all calculations is 7.65%.

Appendix 07 - Peers Selection

To accurately reflect Technoprobe's positioning within the semiconductor ecosystem, our analysis includes both direct competitors (Probe Cards) and Automated Test Equipment (ATE) leaders. These entities share core secular growth drivers linked to increasing node complexity and exhibit homogeneous margin profiles and cyclicality. Peers are classified based on their principal source of revenues: the "Advanced" cluster comprises companies whose growth is fueled by <7nm nodes, High Bandwidth Memory (HBM), and Chiplet adoption (e.g., Advantest, Teradyne, FormFactor); the "Legacy" cluster reflects firms tied to standard smartphone, PC, and traditional automotive volumes. Notably, MPI Corporation is included in the Advanced group, to reflect MPI's strategic pivot toward HBM and AI Chiplets, evidenced by key partnerships such as Xallent, mirroring Technoprobe's own fundamental re-rating as it shifts from cyclical consumer segments to high-growth AI infrastructure. This classification allows for a "Sum-of-the-Parts" relative valuation that captures Technoprobe's transition.

PEERS									
Name	Ticker	Business	Mkt Cap (EUR)	P/E Forward	CAGR:2FY	EBITDA margin	EPS:2027	EV/EBIT	EV/EBITDA
Legacy Group (Consumer & Auto)									
COHU INC	COHU US	**ATE Tester**	1,13B	47,06	16,50%	-2,51%	1,03 €	13,19	24,21
MICRONICS JAPAN	6871 JP	**Probe Cards**	1,95B	25,89	13,00%	27,71%	0,26 €	16,47	11,06
JAPAN ELECTRONIC	6955 JP	**Probe Cards**	332,48M	16,92	11,10%	24,26%	1,57 €	10,1	15.0
CHROMA ATE INC	360 TT	**ATE Tester**	11,51B	38,28	24,50%	28,96%	4,10 €	26,59	32,79
Advanced Testing Leaders (AI)									
TERADYNE INC	TER US	**ATE Tester**	32,78B	47,23	20,60%	25,22%	3,70 €	30,65	36,38
MPI CORP	623 TT	**Probe Cards**	6,57B	46,42	36,30%	29,85%	2,28 €	28,09	36,86
FORMAFACTOR INC	FORM US	**Probe Cards**	4,70B	45,06	7,70%	13,90%	0,61 €	31,05	31,02
ADVANTEST CORP	6857 JP	**ATE Tester**	112,18B	47,43	21,50%	32,73%	8,78 €	36,69	42,43
TECHNOPROBE SPA	PRO IM	**Probe Cards**	10,40B	63,68	21,00%	25,12%	0,35 €	31,05	31,02

Exhibit A serves as a robustness check for our blended P/E valuation strategy. Utilizing the OLS regression model (P/E = 28.52 + 0.57*CAGR), the regression predicts a multiple of 40.5x for Technoprobe's 21% growth profile. This predicted value is highly consistent with our 39.2x blended target multiple derived from the revenue re-rating. The close alignment between the regression and our blended approach statistically validates that our valuation is fundamentally anchored to the sector's growth-valuation frontier.



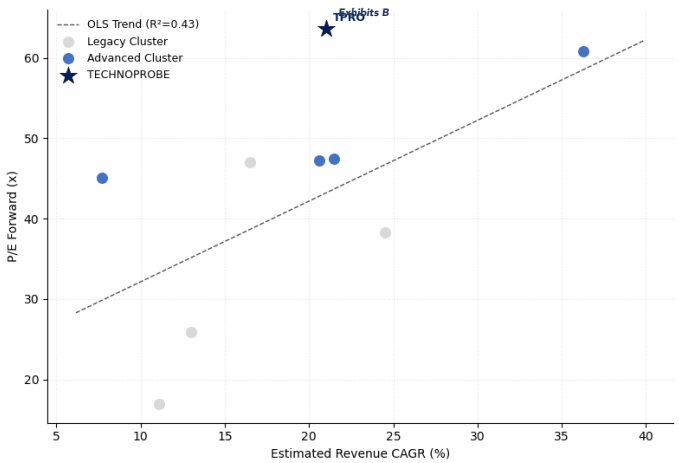


Exhibit B highlights the high correlation between operational efficiency and market pricing. Technoprobe's 25.1% EBITDA margin positions the company on the efficiency frontier alongside top-tier ATE leaders. This regression confirms that TPRO's valuation is a direct reflection of its superior profitability and successful vertical integration strategy. By maintaining margins significantly above the Legacy cluster, TPRO justifies its premium multiple through its ability to scale high-margin AI testing volumes.

Appendix 08 - Montecarlo Simulation

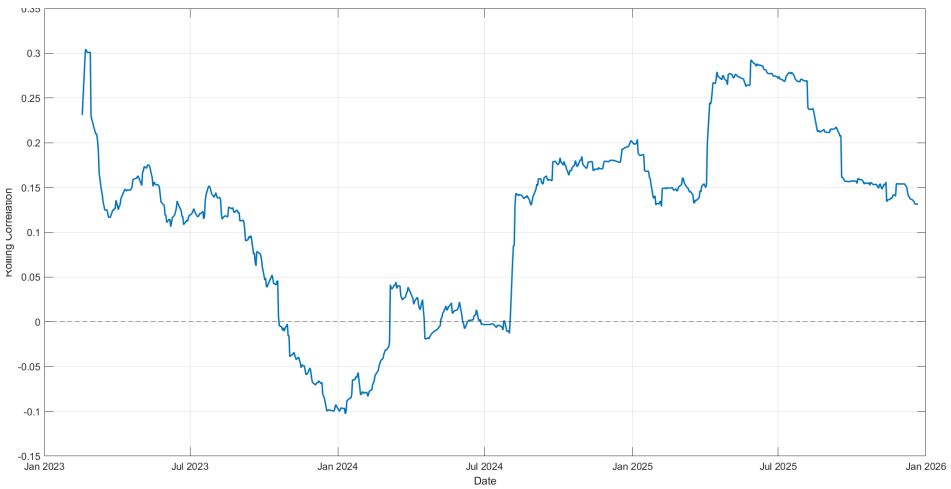
MONTECARLO SIMULATION	DCF ASSUMPTIONS	Distribution	Variance / Limits	Economic Logic / Description
Risk-Free Rate (Rf)	0,04	Normal	σ=0,8% Range: [2,0%,7,0%]	It drives WACC and Nominal Growth. We assume rates normalize around 4% but test stress cases (high inflation vs. stagnatio
WACC	0,0765	Lognormal	σ=0,5	Modeled as Lognormal to strictly prevent negative discount rates.
Beta (β)	0,9	Normal	σ=0,05	We allow it to float slightly to reflect market regime changes
Revenue CAGR (10y)	0,16	Normal	σ=2,5% Range: [5,0%,28,0%]	We simulate the "Through-Cycle" average growth. Correlated with margins (ρ=0.7).
Avg EBITDA Margin	0,43	Normal	σ=2,0% Range: [35,0%,50,0%]	Assumes they maintain high margins on average. Linked to growth: High Growth → High Margin
Operational Ratios(Capex, D&A, WC)	Fixed % of Rev	Deterministic	Capex: 10% D&A: 8% WC: 3%	We hold these constant to isolate the impact of the primary drivers (Growth & Margin) on the valuation

Appendix 09 - Discounted Cash Flow (DCF)

			High Growth Projection Period				Medium Growth Projection Period					
DCF (€M)	**2024A**	**2025E**	**2026E**	**2027E**	**2028E**	**2029E**	**2030E**	**2031E**	**2032E**	**2033E**	**2034E**	**TV**
Revenues	543	627	815	938	1106	1300	1521	1749	1924	2097	2286	
% growth	32,70%	*15,5%*	*30,0%*	*15,0%*	*18,0%*	*17,5%*	*17,0%*	*15,0%*	*10,0%*	*9,0%*	*9,0%*	
EBITDA	136	220	359	417	492	578	677	778	856	933	1017	
% margin	25%	*35,0%*	*44,0%*	*44,5%*	*44,5%*	*44,5%*	*44,5%*	*44,5%*	*44,5%*	*44,5%*	*44,5%*	
EBIT	67	67	277	352	415	487	570	656	722	786	857	
% margin	12,40%	*24%*	*34%*	*38%*	*38%*	*38%*	*38%*	*38%*	*38%*	*38%*	*38%*	
% Tax rate	28%	24%	24%	24%	24%	24%	24%	24%	24%	24%	24%	
NOPAT	48	51	211	267	315	370	433	499	548	598	652	
+D&A	70	69	82	75	77	91	106	122	135	147	160	
%reveneus	12,80%	*11%*	*10%*	*8%*	*7%*	*7%*	*7%*	*7%*	*7%*	*7%*	*7%*	
- Δ Working Capital	16	28	29	32	33	26	30	26	28	21	22	
CF From operations	125	92	263	310	360	435	510	595	655	724	790	
- Net CapEx	94	63	147	122	133	97	122	140	154	168	184	
FCF to the firm	8	29	116	188	227	338	388	455	501	556	606	13.480
%Reveneus	*1%*	*5%*	*14%*	*20%*	*20%*	*26%*	*26%*	*26%*	*26%*	*26%*	*26%*	
% EBIT	*6%*	*13%*	*32%*	*45%*	*46%*	*59%*	*57%*	*58%*	*59%*	*60%*	*60%*	
PV of FCFF			109	163	183	253	270	294	300	310	313	7475
Discounted FCFF				707				1486				

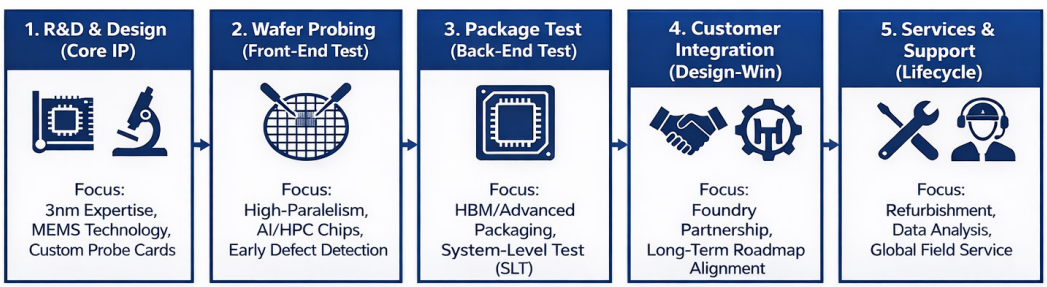
Entreprise Value	**9.760**
NFP	675
Implied Equity Value	**10.435**
N° Shares Outstanding	647
DCF Share Price	**16,1**

Appendix 10 - VIX: Exposure to market uncertainty



Technoprobe's price volatility, measured via the log-difference of daily highs and lows, shows an evolving relationship with market sentiment as tracked by the 252-day rolling correlation with VIX. The correlation remained largely suppressed or slightly negative in early 2024 but experienced a notable upward shift through 2025, reaching a peak near 0.30 by mid-year. This trend highlights an increasing sensitivity to systematic risk factors, suggesting that the stock's idiosyncratic volatility is becoming more aligned with global macro shocks. Although the metric moderated toward 0.13 by January 2026, the underlying trend underscores Technoprobe's significant exposure to shifts in equity market uncertainty.

Appendix 11 - Technoprobe Value Chain



Technoprobe's value chain represents a sophisticated transition from a specialized component manufacturer to a vertically integrated interface solutions provider, strategically positioned to address the complexities of the AI and chiplet era. The process begins with R&D and Core IP, centered on the proprietary TPEG™ MEMS technology, which enables the high-precision, vertical probing required for 3nm and 2nm nodes. This technological bedrock feeds into Wafer Probing (Front-End Test), where the company dominates the high-performance computing (HPC) and AI segments by providing high-parallelism interfaces capable of managing the extreme thermal and electrical demands of modern GPUs. Through the strategic acquisitions of Harbor Electronics and DIS, Technoprobe has successfully extended its reach into Package Test (Back-End Test), closing the loop between wafer-level validation and final system-level testing. This vertical integration (controlling everything from the internal MEMS fab and high-layer-count PCBs to Customer Integration through deep equity alliances like the Teradyne partnership) creates a formidable competitive moat. The chain concludes with a high-margin Services and Support cycle, utilizing a "local-for-local" global footprint to provide essential refurbishment and data analytics, ensuring long-term roadmap alignment and lifecycle sustainability for the world's leading semiconductor foundries.

Appendix 12 - M&A

Year	Transaction	Buy/Sell	Target	Country	Business Unit	Rationale
2019	Merger and Acquisition	Buy	Microfabrica inc.	U.S.	3D MEMS	To expand advanced probe/ micro-component technology platform.
2023	Merger and Acquisition	Buy	Harbor Electronics Inc.	U.S.	PCBs for testing systems	Allowing vertical integration into advanced printed circuit boards.
2023	Merger and Acquisition	Buy	MW Plasma Inc.	U.S.	Process equipment	To bring in construction and design capabilities for microwave systems for CVD and expand technical knowledge for advanced materials.
2024	Merger and Acquisition	Buy	Teradyne DIS department.	U.S.	PCBs and high-performance interfaces	Strengthening competencies in PCBs and high-performance interfaces.
2024	Minority shares	Buy	Teradyne inc.	U.S.	Equity link	Combined transaction in which Teradyne acquired 10% of Technoprobe.
2025	Strategic partnership	-	Advantest Europe GmbH	Germany	PCB supply and joint development	Agreements signed for PCB development and supply with inclusion of supplier priority arrangements.
2025	Minority interests	Buy	Yee Wei Inc.	Taiwan	Governance consolidation	To expand presence in Taiwanese semiconductor market and strengthen its local manufacturing.

The importance of M&A for Technoprobe extends far beyond simple revenue growth, representing a foundational shift toward deep vertical integration and the strategic internalization of critical intellectual property. The 2024 acquisition of DIS (Device Interface Solutions) from Teradyne is a prime example of this economically sound strategy; by bringing the design and production of high-performance Device Interface Boards in-house, Technoprobe has secured control over a critical bottleneck in its value chain. This move not only captures additional margin that would otherwise be lost to third-party suppliers but also creates vital technical synergies between probe card design and interface hardware, which is essential for testing the next generation of complex logic chips used in Artificial Intelligence and High-Performance Computing.

Beyond the immediate financial consolidation, Technoprobe's broader M&A footprint (including the full integration of Microfabrica's 3D MEMS technology and the acquisition of Harbor Electronics) positions the company as a singular end-to-end partner for global chipmakers. Economically, this "buy-and-build" approach leverages the company's significant net financial surplus, which reached €656.3 million by late 2024, to accelerate R&D cycles that would otherwise take years to develop organically. Furthermore, the strategic entry of industry leaders like Teradyne and Advantest into Technoprobe's shareholding structure through reserved capital increases transcends typical investment; it establishes an industrial alliance that guarantees a "privileged perspective" on future technological roadmaps. This ecosystem strategy effectively mitigates the risks of market volatility by anchoring Technoprobe at the center of the global semiconductor test interface market.

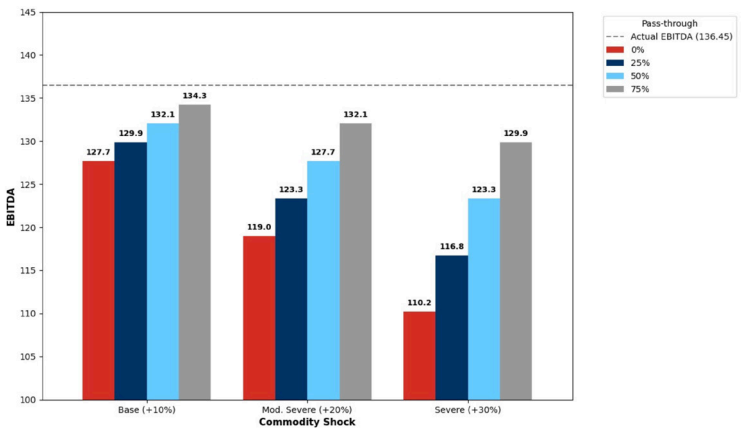
Appendix 14 - ESG Score

Feature	Technoprobe S.p.A.	FormFactor, Inc.	Micronics Japan (MJC)	Japan Electronic Materials (JEM)	Chroma ATE Inc.
Policies & Framework	Structured disclosure with Child Labor Policy and OHSMS.	No standalone sustainability report post-2022. Basic policies only.	"Hierarchy-based Training" for new grads and managers. Dispatches leaders to business schools.	Basic philosophy regarding human rights and safety, but lacks quantitative granularity.	"Drive for Zero" program (all injuries preventable). Zero incidents of unethical conduct.
Welfare & Rights	Comprehensive corporate welfare plan. Code of Business Conduct reflects RBA standards.	Limited disclosure on career progression and gender metrics.	High investment in human capital (95 million yen total education cost). 100% return rate after childcare leave.	"Initial Efforts" category. Lacks detailed diversity statistics.	Principles of equal pay for equal work. Merit-based promotion systems.
Metrics & Stats	Injury rate: 1.65. Gender pay gap: 29%. Women in workforce: 32%.	Minimum social information disclosed.	Male childcare leave: 50% (exceeded 30% target). Female managers: 8.1%.	No published incident rates or detailed diversity statistics.	35% reduction in OSHA recordables. Women in STEM positions: 5.74%.
30% - Social Grade	**3.5**	**1.5**	**3.5**	**1.5**	**3.0**
Oversight Structure	ESG oversight embedded in general governance. CEO and Chair roles separated.	No dedicated ESG strategy. Separation of Chair and CEO.	Compliance and Risk Management Committee reports to Board. CEO and Chairman roles NOT separated.	Board average tenure only 2.6 years. No dedicated ESG committee level supervision.	Separation of CEO and Chair (founder stepping down in 2026). Board training 7.7 hrs/director.
Ethics & Compliance	Global Whistleblowing Policy. Risk-aware management.	Compliance overseen via internal controls.	Strict independence criteria. "MJC Helpline" for whistleblower anonymity. BCP for natural disasters.	Maintains fundamental internal controls and listed on Tokyo Stock Exchange Prime Market.	Perfect score of 5 in corporate governance from FTSE Russell. 44% independent directors.
30% - Governance Grade	**3.0**	**1.5**	**3.0**	**2.0**	**4.0**
Strategy & Targets	No formal transition plan. Scope 1-3 assessment performed.	No formal quantified climate targets publicly disclosed.	Target: 20% reduction in GHG emissions by 2030. Recycles precious metals (gold) from wastewater.	"Environmental Philosophy" focused on quality, but no disclosed 2030 GHG targets.	Net-zero office target (2030) and all facilities (2050). "Green Revenue" accounted for 48.3% of total.
Performance & Initiatives	Renewable energy usage low (1.5%). No internal carbon pricing.	Limited public metrics. Strategy of continuous improvement but weak transparency.	Renewable energy introduction started in 2024. Energy intensity reduced by 7.8% (5-year avg).	Lacks quantitative data to verify transition strategy.	Carbon intensity: 0.39 tons/million NTD. Green power wheeling agreement signed (RE30 goal).
40% - Environmental Grade	**2.0**	**1.0**	**3.0**	**1.5**	**4.5**
FINAL ESG GRADE	**2,75**	**1.30**	**3.15**	**1,65**	**3,9**

Appendix 13 - Most Volatile Raw Materials Price

Raw Material	Role in Probe Cards structure	Major Supply Regions	Major Demand Drivers	Major Price Risks	2026 Outlook
Nickel	• Probe needles • MEMS structures • High-tech applications	Indonesia, New Caledonia, Philippines	• Steel alloys • Electric Vehicles • Batteries • Aerospace & Defense • High-tech applications	• Indonesian export bans • Regulatory changes • Battery demand surges • USD appreciation • LME squeezes	Slightly Bearish • Oversupply from Indonesia • Expected global surplus • Futures in contango
Aluminum	• Heat sinks • Structural components	China, India, Russia, UAE, Canada, Australia	• EVs & Batteries • Aerospace • Construction • Renewables	• China ETS restrictions • Copper price spillover • Mozal shutdown risk	Slightly Bullish • Expected slight global deficit • Mozal closure bringing +400kt deficit • Seen as Copper substitute
Copper	• Electrical pathways • Connectors	Chile, DRC, Peru, China, Indonesia, USA	• Data Centers and AI • Electricity & EVs • Low-carbon power generation • Construction • Transportation	• Supply-demand imbalance • Mining disruptions • Environmental regulations	**Bullish** • Structural deficit • Strong AI/EV demand • Backwardated futures
Titanium	• High-performance elements	China, Mozambique, South Africa, Australia	• Aerospace & Defense • Automotive & Medical • Other industrial metals alloys • Renewables	• Thin supply-demand balance • Energy cost exposure • Cyclical demand recovery	Bullish • Consistent market growth • Upward price pressure • Critical mineral status

Appendix 15 - Raw Materials Price Risk Scenario Analysis



We estimated cost pass-through for Technoprobe as 75% over 12–18 months. This reflects the firm's ability to recover most, but not all, input cost increases in its pricing, given the technical differentiation of its probe cards and the extended qualification cycles that reduce customer price sensitivity. In the short run, contractual rigidity and competitive pressure may limit immediate pass-through, particularly for legacy applications, while more elastic segments or new contracts allow stronger cost recovery over time. Empirical benchmarks from manufacturing and intermediate goods suggest partial short-term pass-through (~60%) that cumulatively approaches 80–90% as contracts are renegotiated and costs become embedded in pricing. Technoprobe's differentiated products, coupled with inelastic demand in high-performance semiconductor testing, support a robust 75% pass-through assumption for the 12–18 month horizon. Our analysis is based on 2 variables: the entity of the shock affecting the price of the basket of raw materials, which represent approximately 30% of COGS; and the rate through which Technoprobe will be able to pass cost inflation to the price paid by customers in a reasonable timeframe of at least 12 months.

We notice how, according to our estimated cost pass-through rate of 75%, based on the market segment and on examples of historical price spikes, the company is able to limit EBITDA reductions to minimal amounts from the base EBITDA of €136.45 M.
For instance, in case of a moderately severe price increase (+20%), this pass-trough mechanism would limit downside to -3.2%, while in case of a much severe increase (+30%), EBITDA impact would stop at -4.9%, a significantly lower reduction compared to more inefficient pass-through management strategies.
Hence, we can state that raw material inflation represents primarily a short-term timing risk, as margins absorb cost increases before price renegotiation, rather than a structural threat to medium-term profitability.

Full Name	Roles	Committees			Background & Contribution
		Control, Risk & Sustainability Committee	Nomination and Remuneration Committee	Related-Parties Committee	
Cristiano Alessandro Crippa	Chairman of the Board of Directors				Background: Technical-commercial diploma and managerial experience in mechanical engineering. Contribution: Contributed to company development and served as Managing Director of DA-TOR S.p.A.
Roberto Alessandro Crippa	Vice President of the Board of Directors				Background: Chemical Engineering degree and inventor of several international patents; recognized among Forbes "Top 100 Italian Managers." Contribution: Director since 1999 and former MD of DA-TOR S.p.A.
Stefano Felici	CEO (Amministratore Delegato)				Background: PhD in Electronic Engineering with extensive semiconductor sector experience. Contribution: Former GM of Technoprobe America and Director across multiple global subsidiaries.
Giulio Sirtori	Independent Non-Executive Director		Chairperson		Background: Senior management roles in trade organizations and Confindustria Lecco. Contribution: Brings expertise in corporate governance and institutional management.
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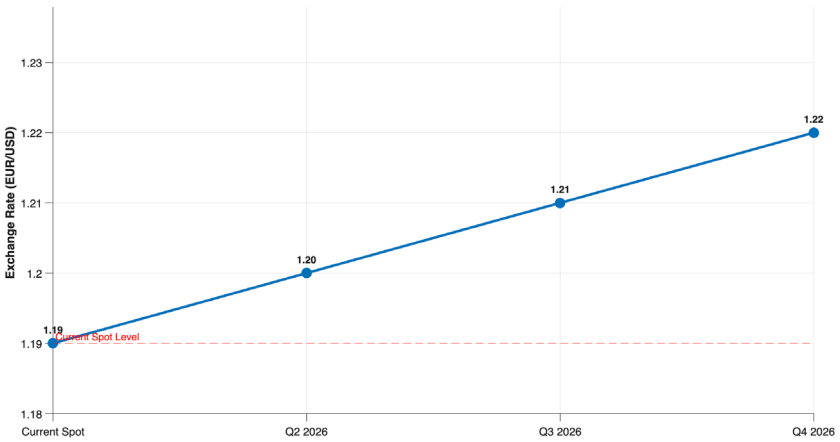
Carlos Ortega Arias-Paz	Independent Non-Executive Director				Background: MBA from Harvard and over 20 years in international investment banking at Goldman Sachs. Contribution: Provides expertise in strategy, finance, and international investments.
Elisabetta Cugnasca	Independent Non-Executive Director				Background: Degree from Bocconi and INSEAD. Former senior auditor with experience in investor relations and internal audit. Contribution: Expertise in financial governance, risk oversight, and capital markets.
Susanna Pedretti	Independent Non-Executive Director	Chairperson			Background: Qualified lawyer with extensive experience in compliance, risk management, and sustainability. Contribution: Provides leadership in governance and related-party committee oversight.
Gregory Stephen Smith	Non-Independent Non-Executive Director				Background: Electronic Engineering degree with a long-standing career at Raytheon and Teradyne. Contribution: Contributes deep industrial know-how as President and CEO of Teradyne Inc.
Antonio Sanna	Independent Non-Executive Director			Chairperson	Background: Manager and General Counsel experience at TIM, Autostrade per l'Italia, and ACEA. Contribution: Oversight on legal, compliance, and risk management matters.
Chih Kuang Yang	Independent Non-Executive Director				Background: PhD in Chemical Engineering with over 20 years in semiconductor wafer fabrication and packaging. Contribution: Founder and General Manager of Yee Wei Inc., Technoprobe's R&D subsidiary.

Appendix 17 - TSMC Projects and their implications

TSMC Project	Partners / Investment	Technological Focus	Strategic Implications for Technoprobe (Risk Diversification)
Arizona, USA	Total investment of $65 billion (across multiple phases).	Advanced nodes (4nm, 3nm and below) for high-performance computing.	Reduces dependency on the Asian supply chain by establishing a "Western Hub." By leveraging the Fremont, CA site, TPRO mitigates geopolitical risk while securing a foothold in the high-margin AI and Consumer Electronics sectors.
Dresden, Germany	Joint Venture (ESMC) with Bosch, Infineon, and NXP.	Specialized semiconductors for the Automotive and Industrial sectors.	Provides critical sectoral diversification. This project allows TPRO to hedge against cyclical downturns in the smartphone market by expanding its presence in the more stable, long-cycle European Automotive and IoT ecosystems.
Kumamoto, Japan	Joint Venture (JASM) with Sony and Denso.	Mature and specialty nodes (12nm to 28nm) for sensors and logic.	Enhances operational resilience by utilizing existing Japanese subsidiaries. It diversifies TPRO's portfolio into Image Sensing (CIS) and Microcontrollers, ensuring revenue stability through essential, high-volume legacy tech applications.

Appendix 18 - Exchange Rate Forecast: The Effect of Fed Rate



Forecasts point to a gradually strengthening euro over 2026, with EUR/USD expected to move from around 1.19 currently to above 1.20 by the end of the year. This view is driven primarily by expectations of Federal Reserve rate cuts as U.S. inflation pressures ease, reducing USD real rate support, alongside a gradual recovery in Eurozone growth supported by fiscal stimulus and lower energy prices. While the pace of euro appreciation is expected to be moderate, the direction of travel implies a structurally less favorable currency environment for Technoprobe, reinforcing its negative exposure to EUR/USD appreciation. In the absence of new, efficient hedging coverage or faster rebalancing of the cost base, aimed at bridging the currency mismatch, a strengthening euro would continue to pressure reported margins and earnings, reinforcing Forex risk as a key sensitivity in the company's financial profile.

Appendix 19 - Exchange Rate Forecast: The Effect of Fed Rate

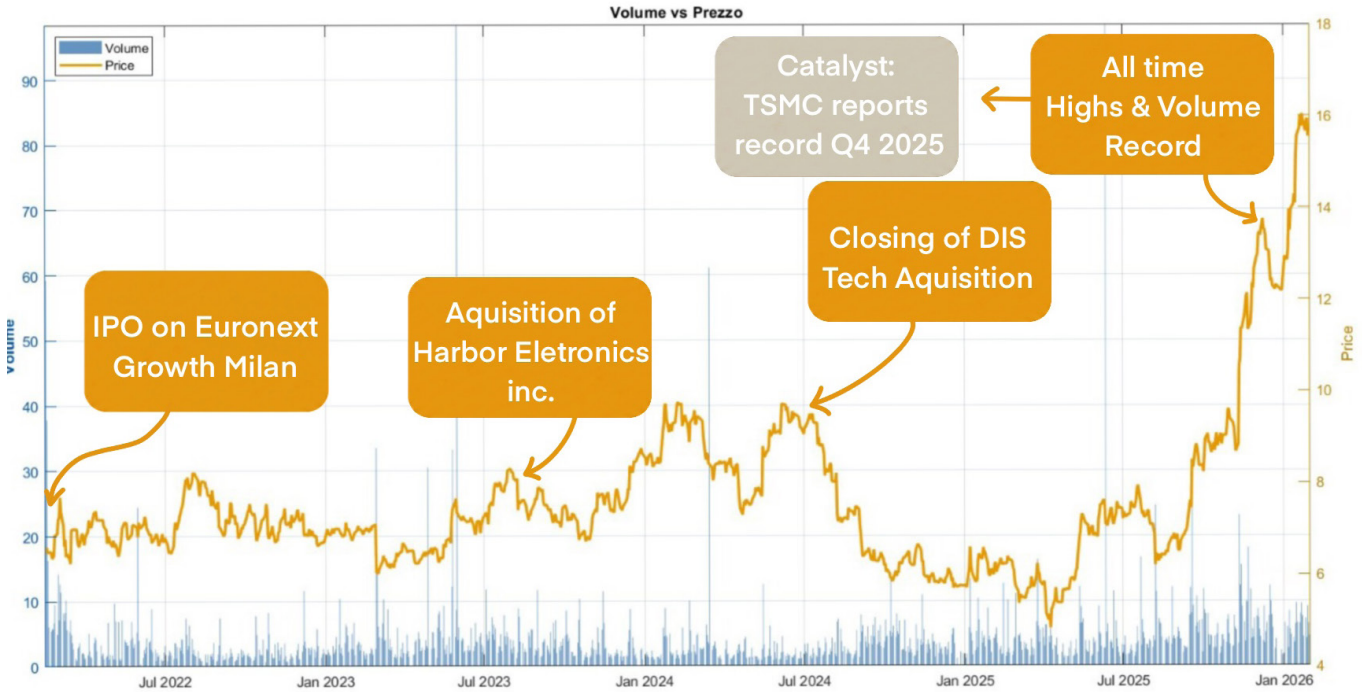
EUR Appreciation	+2%	+5%	+10%
USD	(8,170)	(20,426)	(40,852)
KRW	(480)	(1,198)	(2,396)
TWD	(1,502)	(3,756)	(7,512)
JPY	86	214	428
CHF	2	4	8
GBP	0	2	4
TOTAL FY 2025E	(10,064)	(25,160)	(50,320)

EUR Depreciation	–2%	–5%	–10%
USD	9,030	22,576	45,152
KRW	530	1,324	2,648
TWD	1,660	4,152	8,304
JPY	(94)	(236)	(472)
CHF	(2)	(4)	(8)
GBP	(0)	(2)	(4)
TOTAL FY 2025E	11,124	27,810	55,620

The foreign exchange sensitivity analysis for the projected full-year 2025, built on H1 2025 data and applied to net monetary financial positions denominated in currencies other than EUR, underlines a clear FX exposure for Technoprobe. The analysis features 6 scenarios: EUR appreciation and depreciation by 2%, 5% and 10%, corresponding to base, moderately severe and extreme stress cases. This exposure is significantly driven by the US dollar, which accounts for approximately 81% of the total sensitivity.

The dominance of the USD exposure is a direct consequence of Technoprobe's business structure, characterized by a structural mismatch between its USD-denominated revenues and its primarily EUR-based cost structure. Beyond the primary USD concentration, the analysis identifies secondary, material exposures related to the New Taiwan Dollar (TWD) and the Korean Won (KRW). In contrast, sensitivities to the Japanese Yen (JPY), Swiss Franc (CHF), and British Pound (GBP) remain comparatively immaterial. The net effect of this exposure structure is that foreign exchange movements, particularly in a scenario of sustained euro strength, stand out as a concerning, non-operational risk for FY 2025. The estimated impact is highly concrete, with a 10% move in either direction translating to a pre-tax profit effect exceeding €50 million. This exposure takes on particular significance in view of 2026, when, as it can be inferred from the following EUR/USD forecast, it will be realistic to expect financial losses to materialize.

Product Category	Technology/Product Line	Function and Description	Key Technical Specifications
Wafer Testing (Front-End)	**TPEG™ Vertical MEMS**	High-density probe heads for Logic, SoC, and GPU testing. These units utilize 3D metallic MEMS for ultra-fine pitch applications.[2]	Market share: 60% in Vertical MEMS; Pitch capability down to <30µm.[2]
Wafer Testing (Front-End)	**TPEG™ Mantis**	Targeted for high-volume pad probing in consumer and automotive sectors. Designed for low pad damage and high parallelism.[16]	Pitch: 50µm; CCC: 400mA; Alignment: ±10µm; Lifespan: >1.2M TDs.[16]
Wafer Testing (Front-End)	**TPEG™ T-Series (T1, T3, T4)**	Specialized for Cu-pillar and micro-bump probing. T4 is engineered for extreme pin counts and high mechanical loads.[7]	T1: 80µm pitch on 25µm bumps; T4: >20,000 pins with 100kg total force capacity.[7]
Wafer Testing (Front-End)	**RF+ / XS90 Architecture**	High-frequency probing solutions for 5G, RF-SoC, and high-speed digital interfaces.[7]	Frequency: up to 10 GHz; Enhanced signal integrity via internal GND paths.[12]
Wafer Testing (Front-End)	**Cantilever / Epoxy**	Legacy probing technology for analog, power management, and less complex ICs.[4]	Cost-effective for larger pitches and specialized end-markets.[8]
Final Testing (Back-End)	**Device Interface Boards (DIB)**	High-performance PCBs that connect the tester to the packaged device. Optimized for power and signal integrity.[10]	Multi-layer HDI; Pin pitch down to 60µm; 112 Gbps serial channel support.[14]
Final Testing (Back-End)	**Test Sockets**	Mechanical housings that secure the chip during package-level testing. Includes custom designs for various shapes.[8]	High durability for millions of insertions; Integrated pogo pin contactors.[8]
Final Testing (Back-End)	**Pogo Pins (Spring-Loaded)**	Critical conductive elements within test sockets. Internalized production ensures high quality and low resistance.[8]	Materials: Beryllium Copper/ Stainless Steel; Gold plating for conductivity.[21]
Final Testing (Back-End)	**FusionLink Architecture**	Disaggregated hardware architecture for AI/HPC. Combines PCB motherboards with MLO/HDI substrates.[12]	Optimized for high power density and 112 Gbps speeds; Redesigned development cycle.[14]
System-Level / Debug	**Athena System**	Advanced automated system for chip testing, debugging, and characterization.[24]	Weight: 9,038 kg; Channels: up to 18,432; Vacuum and air pressure utilities.[24]



1. **The Debut: IPO on Euronext Growth Milan (Feb 2022)**
   Despite high volume, the price didn't explode immediately: this indicates the market was waiting for proof of scalability beyond the initial IPO hype.

2. **Acquisition of Harbor Electronics (Aug 2023)**
   By acquiring Harbor Electronics, Technoprobe stopped being just an assembler and became a producer of its own advanced PCBs. The market reacted positively (price moved up) because this reduced costs and dependency on external suppliers.

3. **Closing of DIS Tech Acquisition (May 2024)**
   The closing of the DIS Tech deal involved issuing new shares to Teradyne (bringing the total to ~647M). The subsequent price dip suggests the market was digesting the dilution and the temporary drop in revenue during the semiconductor cyclical trough.

4. **All-Time Highs & Volume Record (Jan 2026)**
   The massive Capex plan announced by TSMC ($52-56B) signaled that the demand for 2nm and AI chips was real and immediate. Because Technoprobe had spent the previous years acquiring DIS and Harbor, they were ready to supply the testing gear for this exact demand.